PCF85162

32 × 4 universal LCD driver for low multiplex rates

Rev. 5 — 17 December 2014 Product data sheet

1. General description

The PCF85162 is a peripheral device which interfaces to almost any Liquid Crystal Display (LCD)[1] with low multiplex rates. It generates the drive signals for any static or multiplexed LCD containing up to four backplanes and up to 32 segments. It can be easily cascaded for larger LCD applications. The PCF85162 is compatible with most microcontrollers and communicates via the two-line bidirectional I^2C-bus. Communication overheads are minimized by a display RAM with auto-incremented addressing, by hardware subaddressing, and by display memory switching (static and duplex drive modes).

For a selection of NXP LCD segment drivers, see Table 25 on page 44.

2. Features and benefits

- Single chip LCD controller and driver
- Selectable backplane drive configuration: static, 2, 3, or 4 backplane multiplexing
- Selectable display bias configuration: static, $\frac{1}{2}$, or $\frac{1}{3}$
- Internal LCD bias generation with voltage-follower buffers
- 32 segment drives:
  - Up to 16 7-segment numeric characters
  - Up to 8 14-segment alphanumeric characters
  - Any graphics of up to 128 segments/elements
- 32 × 4-bit RAM for display data storage
- Display memory bank switching in static and duplex drive modes
- Versatile blinking modes
- Independent supplies possible for LCD and logic voltages
- Wide power supply range: from 1.8 V to 5.5 V
- Wide logic LCD supply range:
  - From 2.5 V for low-threshold LCDs
  - Up to 6.5 V for guest-host LCDs and high-threshold twisted nematic LCDs
- Low power consumption
- 400 kHz I^2C-bus interface
- No external components required
- Manufactured in silicon gate CMOS process

1. The definition of the abbreviations and acronyms used in this data sheet can be found in Section 21.

3. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
PCF85162T	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	SOT362-1

3.1 Ordering options

Table 2. Ordering options

Product type number	IC revision	Sales item (12NC)	Delivery form
PCF85162T/1	1	935290708118	tape and reel, 13 inch

4. Marking

Table 3. Marking codes

Product type number	Marking code
PCF85162T/1	PCF85162T

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

5. Block diagram

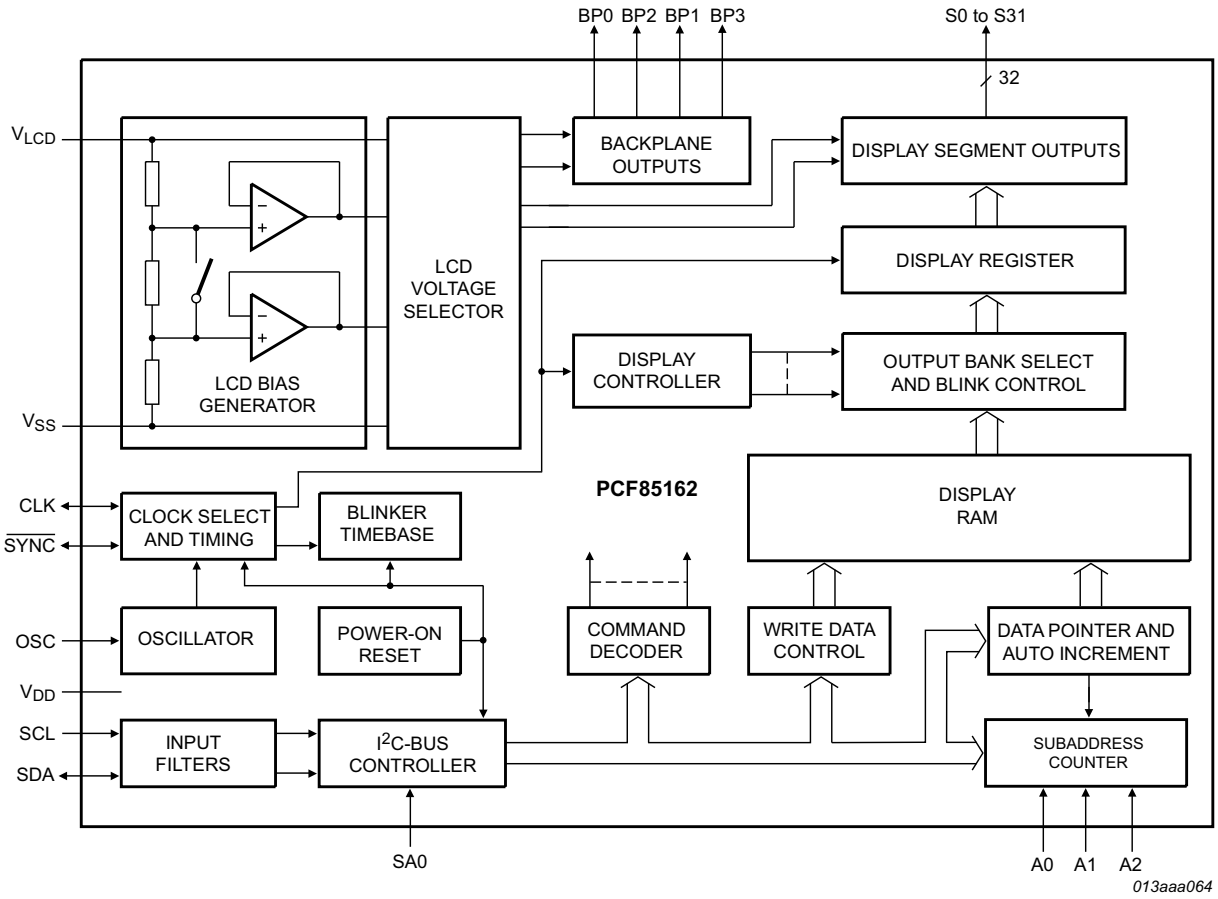


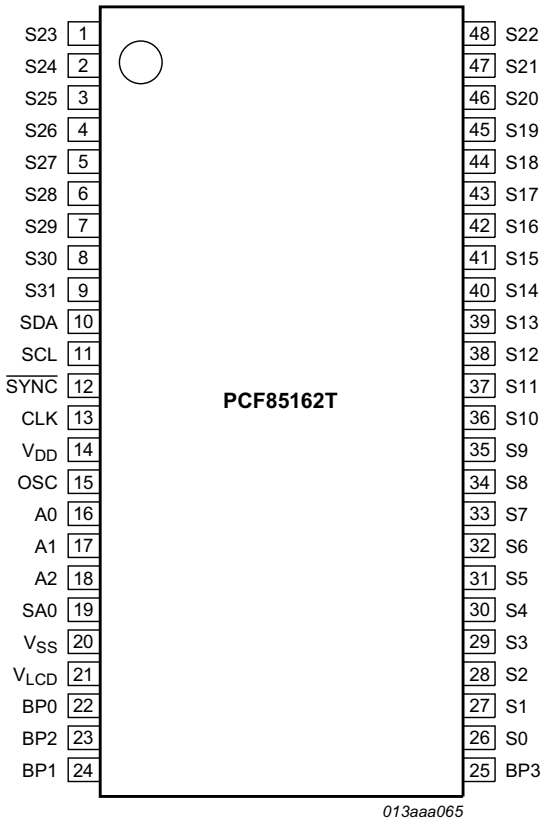
Fig 1. Block diagram of PCF85162

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

6. Pinning information

6.1 Pinning



Top view. For mechanical details, see Figure 28.

Fig 2. Pin configuration for TSSOP48 (PCF85162T)

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

6.2 Pin description

Table 4. Pin description

Input or input/output pins must always be at a defined level (V_{SS} or V_{DD}) unless otherwise specified.

Symbol	Pin	Type	Description
SDA	10	input/output	I^2C-bus serial data line
SCL	11	input	I^2C-bus serial clock
$\overline{SYNC}$	12	input/output	cascade synchronization input or output; if not used it must be left open
CLK	13	input/output	clock line
V_{DD}	14	supply	supply voltage
OSC	15	input	internal oscillator enable
A0 to A2	16 to 18	input	subaddress inputs
SA0	19	input	I^2C-bus address input
V_{SS}	20	supply	ground supply voltage
V_{LCD}	21	supply	LCD supply voltage
BP0 to BP3	22 to 25	output	LCD backplane outputs
S0 to S22, S23 to S31	26 to 48, 1 to 9	output	LCD segment outputs

7. Functional description

The PCF85162 is a versatile peripheral device designed to interface between any microcontroller to a wide variety of LCD segment or dot matrix displays. It can directly drive any static or multiplexed LCD containing up to four backplanes and up to 32 segments.

7.1 Commands of PCF85162

The commands available to the PCF85162 are defined in Table 5.

Table 5. Definition of PCF85162 commands

Bit position labeled as - is not used.

Command	Operation code								Reference
Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**	
mode-set	C	1	0	-	E	B	M[1:0]		Table 7
load-data-pointer	C	0	0	P[4:0]					Table 8
device-select	C	1	1	0	0	A[2:0]			Table 9
bank-select	C	1	1	1	1	0	I	O	Table 10
blink-select	C	1	1	1	0	AB	BF[1:0]		Table 11

All available commands carry a continuation bit C in their most significant bit position as shown in Figure 21. When this bit is set logic 1, it indicates that the next byte of the transfer to arrive will also represent a command. If this bit is set logic 0, it indicates that the command byte is the last in the transfer. Further bytes will be regarded as display data (see Table 6).

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

Table 6. C bit description

Bit	Symbol	Value	Description
7	C		**continue bit**
		0	last control byte in the transfer; next byte will be regarded as display data
		1	control bytes continue; next byte will be a command too

7.1.1 Command: mode-set

The mode-set command allows configuring the multiplex mode, the bias levels and enabling or disabling the display.

Table 7. Mode-set command bit description

Bit	Symbol	Value	Description
7	C	0, 1	see Table 6
6 to 5	-	10	fixed value
4	-	-	unused
3	E		**display status**[1]
		0[2]	disabled (blank)[3]
		1	enabled
2	B		**LCD bias configuration**[4]
		0[2]	$\frac{1}{3}$ bias
		1	$\frac{1}{2}$ bias
1 to 0	M[1:0]		**LCD drive mode selection**
		01	static; BP0
		10	1:2 multiplex; BP0, BP1
		11	1:3 multiplex; BP0, BP1, BP2
		00[2]	1:4 multiplex; BP0, BP1, BP2, BP3

[1] The possibility to disable the display allows implementation of blinking under external control.

[2] Default value.

[3] The display is disabled by setting all backplane and segment outputs to V_{LCD}.

[4] Not applicable for static drive mode.

7.1.2 Command: load-data-pointer

The load-data-pointer command defines the display RAM address where the following display data will be sent to.

Table 8. Load-data-pointer command bit description

See Section 7.6.1.

Bit	Symbol	Value	Description
7	C	0, 1	see Table 6
6 to 5	-	00	fixed value
4 to 0	P[4:0]	00000[1] to 11111	5 bit binary value, 0 to 31; transferred to the data pointer to define one of 32 display RAM addresses

[1] Default value.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

7.1.3 Command: device-select

The device-select command allows defining the subaddress counter value.

Table 9. Device-select command bit description

See Section 7.6.2.

Bit	Symbol	Value	Description
7	C	0, 1	see Table 6
6 to 3	-	1100	fixed value
2 to 0	A[2:0]	000[1] to 111	3 bit binary value, 0 to 7; transferred to the subaddress counter to define one of eight hardware subaddresses

[1] Default value.

7.1.4 Command: bank-select

The bank-select command controls where data is written to RAM and where it is displayed from.

Table 10. Bank-select command bit description

See Section 7.6.5.

Bit	Symbol	Value	Description	
			Static	**1:2 multiplex[1]**
7	C	0, 1	see Table 6	
6 to 2	-	11110	fixed value	
1	I		**input bank selection**; storage of arriving display data	
		0[2]	RAM row 0	RAM rows 0 and 1
		1	RAM row 2	RAM rows 2 and 3
0	O		**output bank selection**; retrieval of LCD display data	
		0[2]	RAM row 0	RAM rows 0 and 1
		1	RAM row 2	RAM rows 2 and 3

[1] The bank-select command has no effect in 1:3 and 1:4 multiplex drive modes.

[2] Default value.

7.1.5 Command: blink-select

The blink-select command allows configuring the blink mode and the blink frequency.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

Table 11. Blink-select command bit description

See Section 7.1.5.1.

Bit	Symbol	Value	Description
7	C	0, 1	see Table 6
6 to 3	-	1110	fixed value
2	AB		**blink mode selection**
		0[1]	normal blinking[2]
		1	alternate RAM bank blinking[3]
1 to 0	BF[1:0]		**blink frequency selection**
		00[1]	off
		01	1
		10	2
		11	3

[1] Default value.

[2] Normal blinking is assumed when the LCD multiplex drive modes 1:3 or 1:4 are selected.

[3] Alternate RAM bank blinking does not apply in 1:3 and 1:4 multiplex drive modes.

7.1.5.1 Blinking

The display blinking capabilities of the PCF85162 are very versatile. The whole display can blink at frequencies selected by the blink-select command (see Table 11). The blink frequencies are derived from the clock frequency. The ratio between the clock and blink frequencies depends on the blink mode selected (see Table 12).

An additional feature is for an arbitrary selection of LCD segments/elements to blink. This applies to the static and 1:2 multiplex drive modes and can be implemented without any communication overheads. By means of the output bank selector, the displayed RAM banks are exchanged with alternate RAM banks at the blink frequency. This mode can also be specified by the blink-select command.

In the 1:3 and 1:4 multiplex modes, where no alternative RAM bank is available, groups of LCD segments/elements can blink by selectively changing the display RAM data at fixed time intervals.

The entire display can blink at a frequency other than the nominal blink frequency. This can be effectively performed by resetting and setting the display enable bit E at the required rate using the mode-set command (see Table 7).

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

Table 12. Blink frequencies

Blink mode	Blink frequency equation[1]
off	-
1	$f_{blink} = \frac{f_{clk}}{768}$
2	$f_{blink} = \frac{f_{clk}}{1536}$
3	$f_{blink} = \frac{f_{clk}}{3072}$

[1] The blink frequency is proportional to the clock frequency (f_{clk}). For the range of the clock frequency see Table 20.

7.2 Power-On Reset (POR)

At power-on the PCF85162 resets to the following starting conditions:

- All backplane and segment outputs are set to V_{LCD}
- The selected drive mode is: 1:4 multiplex with $\frac{1}{3}$ bias
- Blinking is switched off
- Input and output bank selectors are reset
- The I^2C-bus interface is initialized
- The data pointer and the subaddress counter are cleared (set to logic 0)
- The display is disabled (bit E = 0, see Table 7)

Remark: Do not transfer data on the I^2C-bus for at least 1 ms after a power-on to allow the reset action to complete.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

7.3 Possible display configurations

The possible display configurations of the PCF85162 depend on the number of active backplane outputs required. A selection of display configurations is shown in Table 13. All of these configurations can be implemented in the typical system shown in Figure 4.

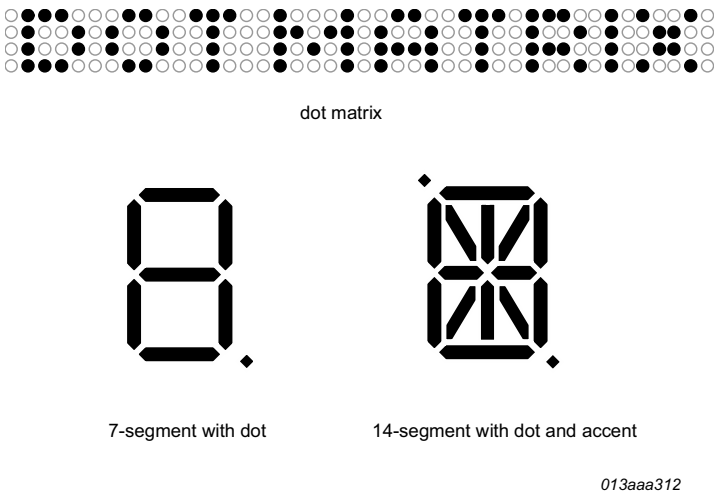


Fig 3. Example of displays suitable for PCF85162

Table 13. Selection of possible display configurations

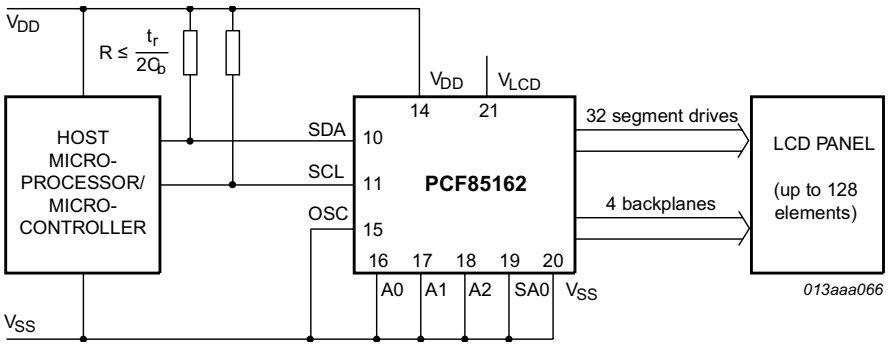
Number of				
Backplanes	**Icons**	**Digits/Characters**		**Dot matrix: segments/ elements**
		7-segment[1]	**14-segment[2]**	
4	128	16	8	128 dots (4 × 32)
3	96	12	6	96 dots (3 × 32)
2	64	8	4	64 dots (2 × 32)
1	32	4	2	32 dots (1 × 32)

[1] 7 segment display has 8 segments/elements including the decimal point.

[2] 14 segment display has 16 segments/elements including decimal point and accent dot.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.



The resistance of the power lines must be kept to a minimum.

Fig 4. Typical system configuration

The host microcontroller maintains the 2-line I²C-bus communication channel with the PCF85162. The internal oscillator is enabled by connecting pin OSC to pin V_{SS}. The appropriate biasing voltages for the multiplexed LCD waveforms are generated internally. The only other connections required to complete the system are the power supplies (V_{DD}, V_{SS}, and V_{LCD}) and the LCD panel chosen for the application.

7.3.1 LCD bias generator

Fractional LCD biasing voltages are obtained from an internal voltage divider consisting of three impedances connected in series between V_{LCD} and V_{SS}. The center impedance is bypassed by switch if the ½ bias voltage level for the 1:2 multiplex drive mode configuration is selected. The LCD voltage can be temperature compensated externally, using the supply to pin V_{LCD}.

7.3.2 Display register

The display register holds the display data while the corresponding multiplex signals are generated.

7.3.3 LCD voltage selector

The LCD voltage selector coordinates the multiplexing of the LCD in accordance with the selected LCD drive configuration. The operation of the voltage selector is controlled by the mode-set command from the command decoder. The biasing configurations that apply to the preferred modes of operation, together with the biasing characteristics as functions of V_{LCD} and the resulting discrimination ratios (D) are given in Table 14.

Discrimination is a term which is defined as the ratio of the on and off RMS voltage across a segment. It can be thought of as a measurement of contrast.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

Table 14. Biasing characteristics

LCD drive mode	Number of:		LCD bias configuration	$\frac{V_{off(RMS)}}{V_{LCD}}$	$\frac{V_{on(RMS)}}{V_{LCD}}$	$D = \frac{V_{on(RMS)}}{V_{off(RMS)}}$
	Backplanes	Levels				
static	1	2	static	0	1	∞
1:2 multiplex	2	3	½	0.354	0.791	2.236
1:2 multiplex	2	4	⅓	0.333	0.745	2.236
1:3 multiplex	3	4	⅓	0.333	0.638	1.915
1:4 multiplex	4	4	⅓	0.333	0.577	1.732

A practical value for V_{LCD} is determined by equating $V_{off(RMS)}$ with a defined LCD threshold voltage ($V_{th(off)}$), typically when the LCD exhibits approximately 10 % contrast. In the static drive mode a suitable choice is $V_{LCD} > 3V_{th(off)}$.

Multiplex drive modes of 1:3 and 1:4 with ½ bias are possible but the discrimination and hence the contrast ratios are smaller.

Bias is calculated by $\frac{1}{1+a}$, where the values for a are

a = 1 for ½ bias

a = 2 for ⅓ bias

The RMS on-state voltage ($V_{on(RMS)}$) for the LCD is calculated with Equation 1:

$$V_{on(RMS)} = V_{LCD}\sqrt{\frac{a^2+2a+n}{n\times(1+a)^2}} \quad (1)$$

where the values for n are

n = 1 for static drive mode

n = 2 for 1:2 multiplex drive mode

n = 3 for 1:3 multiplex drive mode

n = 4 for 1:4 multiplex drive mode

The RMS off-state voltage ($V_{off(RMS)}$) for the LCD is calculated with Equation 2:

$$V_{off(RMS)} = V_{LCD}\sqrt{\frac{a^2-2a+n}{n\times(1+a)^2}} \quad (2)$$

Discrimination is the ratio of $V_{on(RMS)}$ to $V_{off(RMS)}$ and is determined from Equation 3:

$$D = \frac{V_{on(RMS)}}{V_{off(RMS)}} = \sqrt{\frac{a^2+2a+n}{a^2-2a+n}} \quad (3)$$

Using Equation 3, the discrimination for an LCD drive mode of 1:3 multiplex with ½ bias is $\sqrt{3} = 1.732$ and the discrimination for an LCD drive mode of 1:4 multiplex with ½ bias is $\frac{\sqrt{21}}{3} = 1.528$.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

The advantage of these LCD drive modes is a reduction of the LCD full scale voltage V_{LCD} as follows:

- 1:3 multiplex (½ bias): $V_{LCD} = \sqrt{6} \times V_{off(RMS)} = 2.449 V_{off(RMS)}$
- 1:4 multiplex (½ bias): $V_{LCD} = \left[\frac{(4 \times \sqrt{3})}{3}\right] = 2.309 V_{off(RMS)}$

These compare with $V_{LCD} = 3V_{off(RMS)}$ when ⅓ bias is used.

It should be noted that V_{LCD} is sometimes referred as the LCD operating voltage.

7.3.3.1 Electro-optical performance

Suitable values for $V_{on(RMS)}$ and $V_{off(RMS)}$ are dependent on the LCD liquid used. The RMS voltage, at which a pixel will be switched on or off, determine the transmissibility of the pixel.

For any given liquid, there are two threshold values defined. One point is at 10 % relative transmission (at $V_{th(off)}$) and the other at 90 % relative transmission (at $V_{th(on)}$), see Figure 5. For a good contrast performance, the following rules should be followed:

$$V_{on(RMS)} \geq V_{th(on)} \quad (4)$$

$$V_{off(RMS)} \leq V_{th(off)} \quad (5)$$

$V_{on(RMS)}$ and $V_{off(RMS)}$ are properties of the display driver and are affected by the selection of a, n (see Equation 1 to Equation 3) and the V_{LCD} voltage.

$V_{th(off)}$ and $V_{th(on)}$ are properties of the LCD liquid and can be provided by the module manufacturer. $V_{th(off)}$ is sometimes just named V_{th}. $V_{th(on)}$ is sometimes named saturation voltage V_{sat}.

It is important to match the module properties to those of the driver in order to achieve optimum performance.

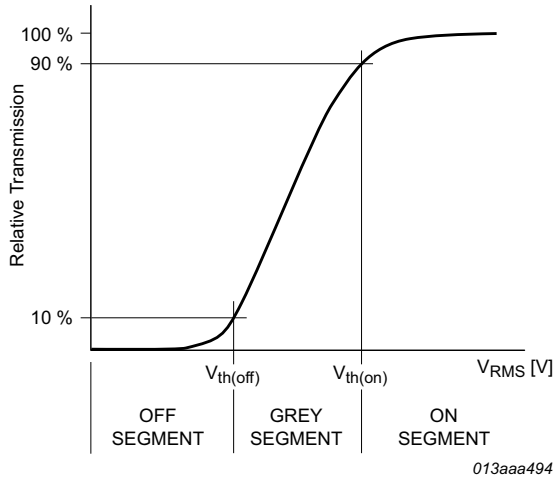


Fig 5. Electro-optical characteristic: relative transmission curve of the liquid

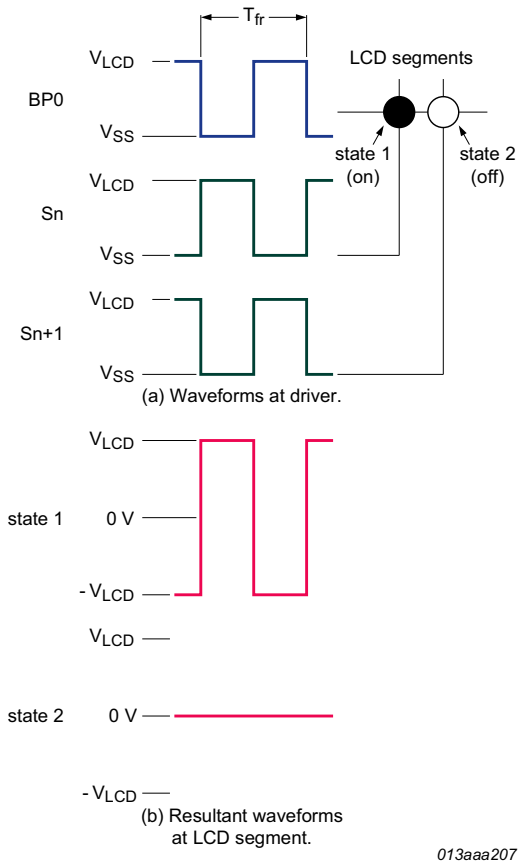
All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

7.3.4 LCD drive mode waveforms

7.3.4.1 Static drive mode

The static LCD drive mode is used when a single backplane is provided in the LCD. The backplane (BPn) and segment (Sn) drive waveforms for this mode are shown in Figure 6.



$V_{state1}(t) = V_{Sn}(t) - V_{BP0}(t)$.

$V_{on(RMS)} = V_{LCD}$.

$V_{state2}(t) = V_{(Sn + 1)}(t) - V_{BP0}(t)$.

$V_{off(RMS)} = 0$ V.

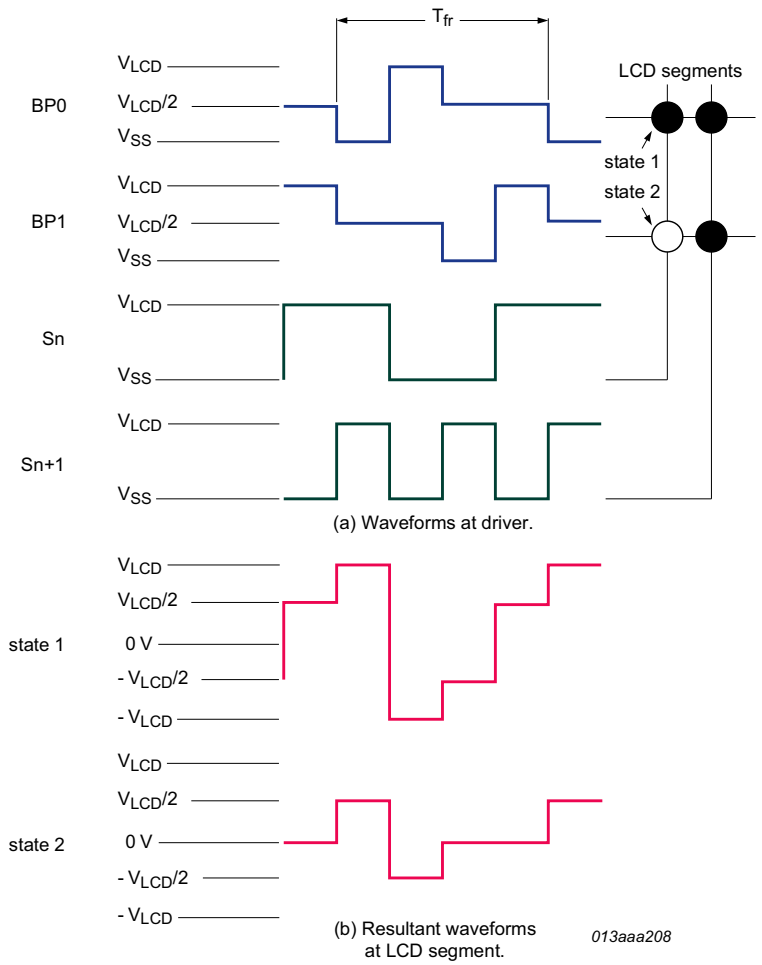
Fig 6. Static drive mode waveforms

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

7.3.4.2 1:2 Multiplex drive mode

When two backplanes are provided in the LCD, the 1:2 multiplex mode applies. The PCF85162 allows the use of ½ bias or ⅓ bias in this mode as shown in Figure 7 and Figure 8.



$V_{state1}(t) = V_{Sn}(t) - V_{BP0}(t)$.

$V_{on(RMS)} = 0.791V_{LCD}$.

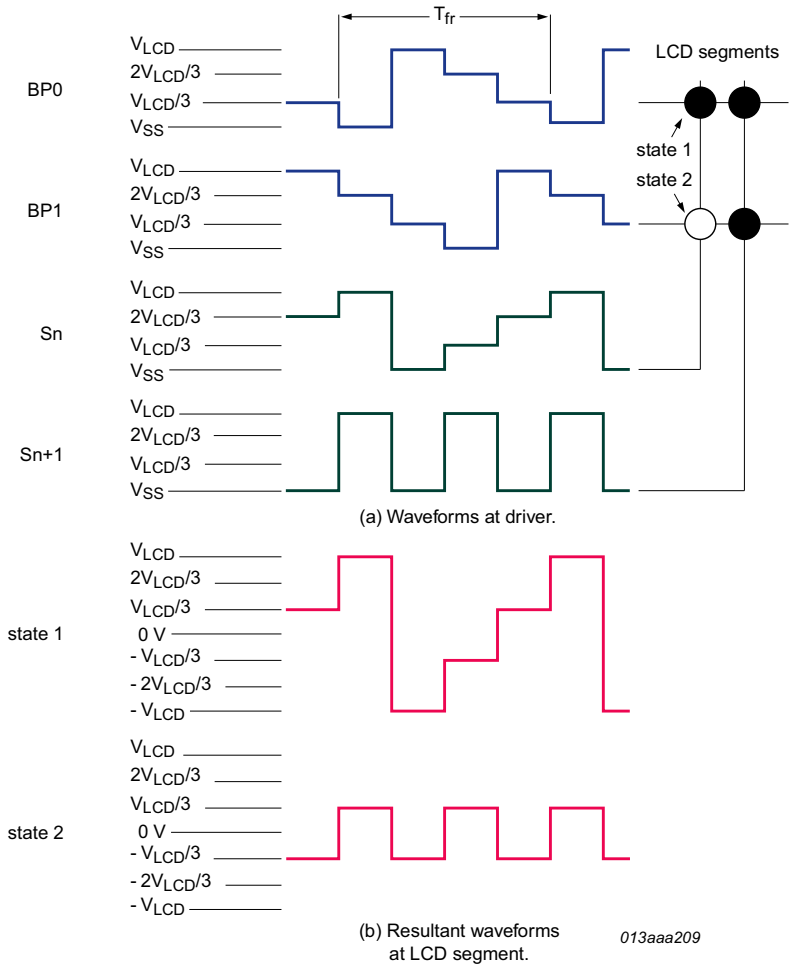
$V_{state2}(t) = V_{Sn}(t) - V_{BP1}(t)$.

$V_{off(RMS)} = 0.354V_{LCD}$.

Fig 7. Waveforms for the 1:2 multiplex drive mode with ½ bias

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.



$V_{state1}(t) = V_{Sn}(t) - V_{BP0}(t)$.

$V_{on(RMS)} = 0.745V_{LCD}$.

$V_{state2}(t) = V_{Sn}(t) - V_{BP1}(t)$.

$V_{off(RMS)} = 0.333V_{LCD}$.

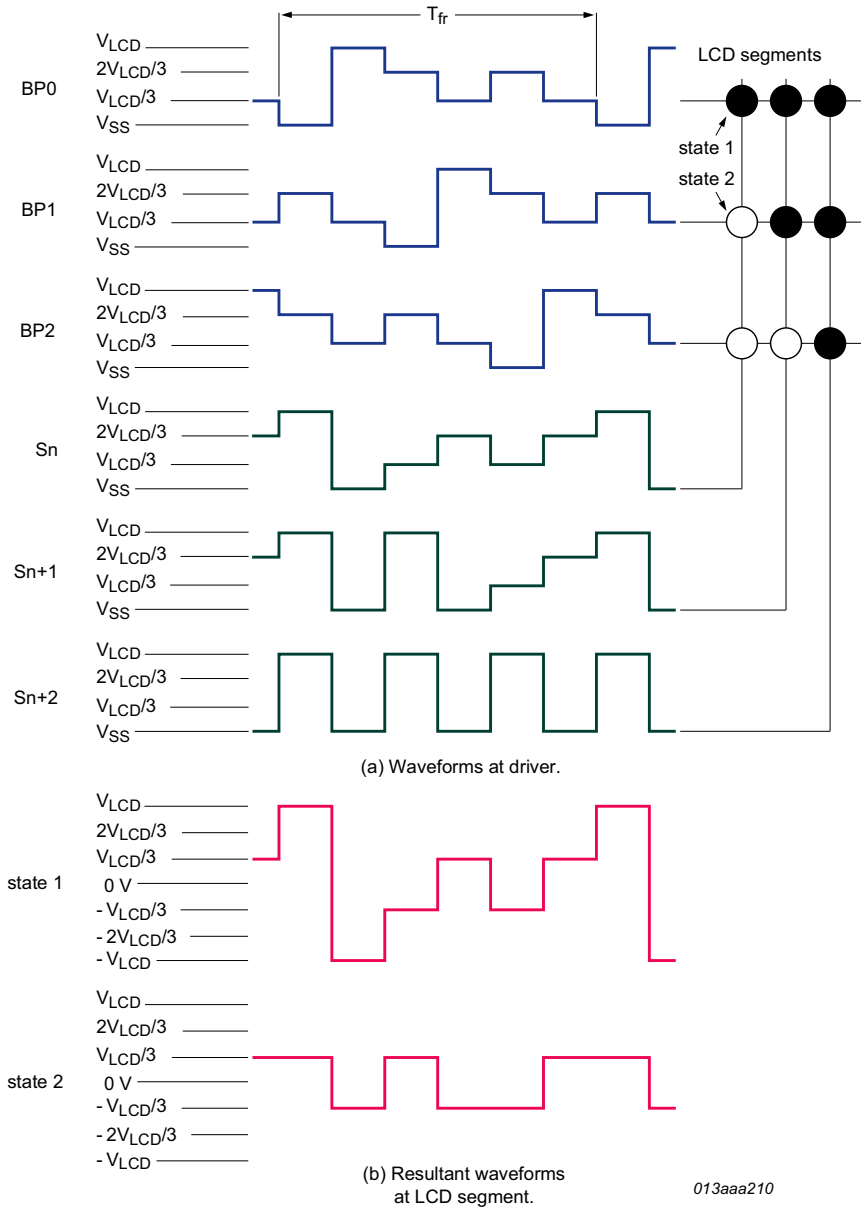
Fig 8. Waveforms for the 1:2 multiplex drive mode with ⅓ bias

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

7.3.4.3 1:3 Multiplex drive mode

When three backplanes are provided in the LCD, the 1:3 multiplex drive mode applies, as shown in Figure 9.



$V_{state1}(t) = V_{Sn}(t) - V_{BP0}(t)$.

$V_{on(RMS)} = 0.638V_{LCD}$.

$V_{state2}(t) = V_{Sn}(t) - V_{BP1}(t)$.

$V_{off(RMS)} = 0.333V_{LCD}$.

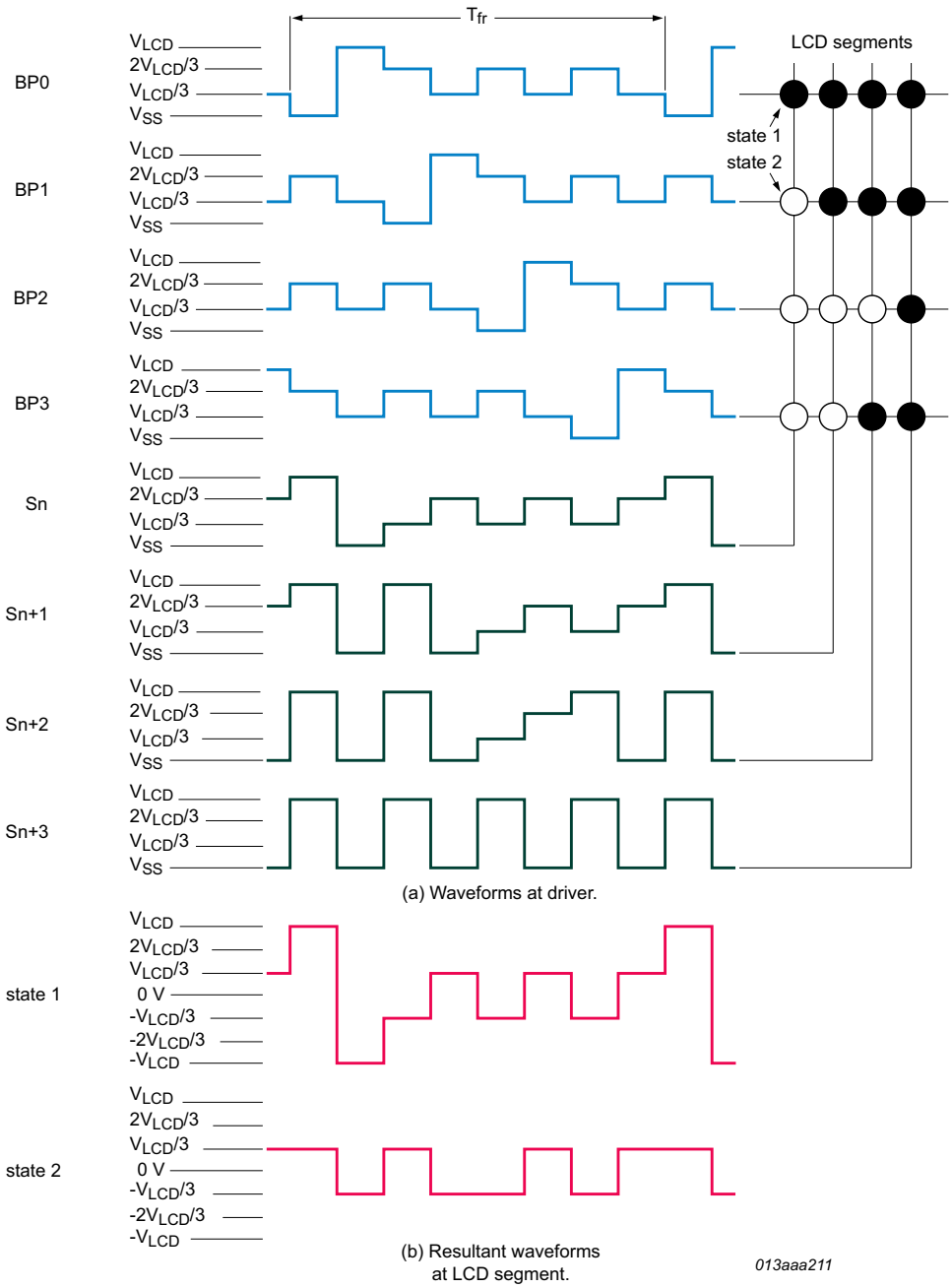
Fig 9. Waveforms for the 1:3 multiplex drive mode with ⅓ bias

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

7.3.4.4 1:4 Multiplex drive mode

When four backplanes are provided in the LCD, the 1:4 multiplex drive mode applies as shown in Figure 10.



$V_{state1}(t) = V_{Sn}(t) - V_{BP0}(t)$.

$V_{on(RMS)} = 0.577V_{LCD}$.

$V_{state2}(t) = V_{Sn}(t) - V_{BP1}(t)$.

$V_{off(RMS)} = 0.333V_{LCD}$.

Fig 10. Waveforms for the 1:4 multiplex drive mode with ⅓ bias

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

7.4 Oscillator

7.4.1 Internal clock

The internal logic of the PCF85162 and its LCD drive signals are timed either by its internal oscillator or by an external clock. The internal oscillator is enabled by connecting pin OSC to pin V_{SS}. If the internal oscillator is used, the output from pin CLK can be used as the clock signal for several PCF85162 in the system that are connected in cascade.

7.4.2 External clock

Pin CLK is enabled as an external clock input by connecting pin OSC to V_{DD}. The LCD frame frequency is determined by the clock frequency (f_{clk}).

Remark: A clock signal must always be supplied to the device; removing the clock may freeze the LCD in a DC state, which is not suitable for the liquid crystal.

7.4.3 Timing

The PCF85162 timing controls the internal data flow of the device. This includes the transfer of display data from the display RAM to the display segment outputs. In cascaded applications, the correct timing relationship between each PCF85162 in the system is maintained by the synchronization signal at pin $\overline{\text{SYNC}}$. The timing also generates the LCD frame frequency signal. The frame frequency signal is a fixed division of the clock frequency from either the internal or an external clock: $f_{fr} = \frac{f_{clk}}{24}$

7.5 Backplane and segment outputs

7.5.1 Backplane outputs

The LCD drive section includes four backplane outputs BP0 to BP3 which must be connected directly to the LCD. The backplane output signals are generated in accordance with the selected LCD drive mode. If less than four backplane outputs are required, the unused outputs can be left open-circuit.

- In 1:3 multiplex drive mode, BP3 carries the same signal as BP1, therefore these two adjacent outputs can be tied together to give enhanced drive capabilities
- In 1:2 multiplex drive mode, BP0 and BP2, respectively, BP1 and BP3 carry the same signals and may also be paired to increase the drive capabilities
- In static drive mode the same signal is carried by all four backplane outputs and they can be connected in parallel for very high drive requirements

7.5.2 Segment outputs

The LCD drive section includes 32 segment outputs (S0 to S31) which should be connected directly to the LCD. The segment output signals are generated in accordance with the multiplexed backplane signals and with data residing in the display register. When less than 32 segment outputs are required, the unused segment outputs should be left open-circuit.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

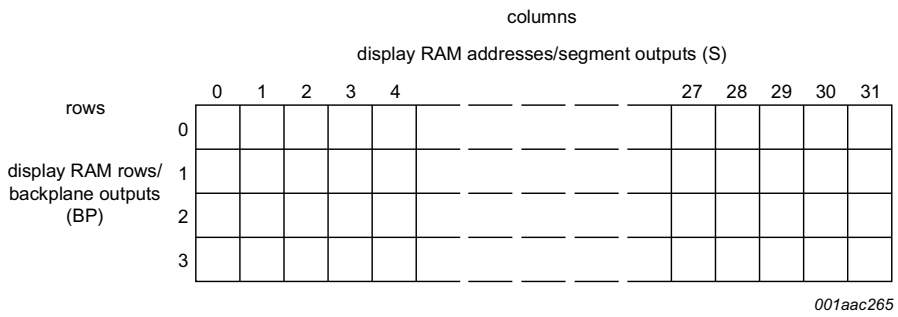
7.6 Display RAM

The display RAM is a static 32 × 4-bit RAM which stores LCD data. There is a one-to-one correspondence between

- the bits in the RAM bitmap and the LCD segments/elements
- the RAM columns and the segment outputs
- the RAM rows and the backplane outputs.

A logic 1 in the RAM bitmap indicates the on-state of the corresponding LCD element; similarly, a logic 0 indicates the off-state.

The display RAM bitmap, Figure 11, shows the rows 0 to 3 which correspond with the backplane outputs BP0 to BP3, and the columns 0 to 31 which correspond with the segment outputs S0 to S31. In multiplexed LCD applications the segment data of the first, second, third, and fourth row of the display RAM are time-multiplexed with BP0, BP1, BP2, and BP3 respectively.



The display RAM bitmap shows the direct relationship between the display RAM column and the segment outputs; and between the bits in a RAM row and the backplane outputs.

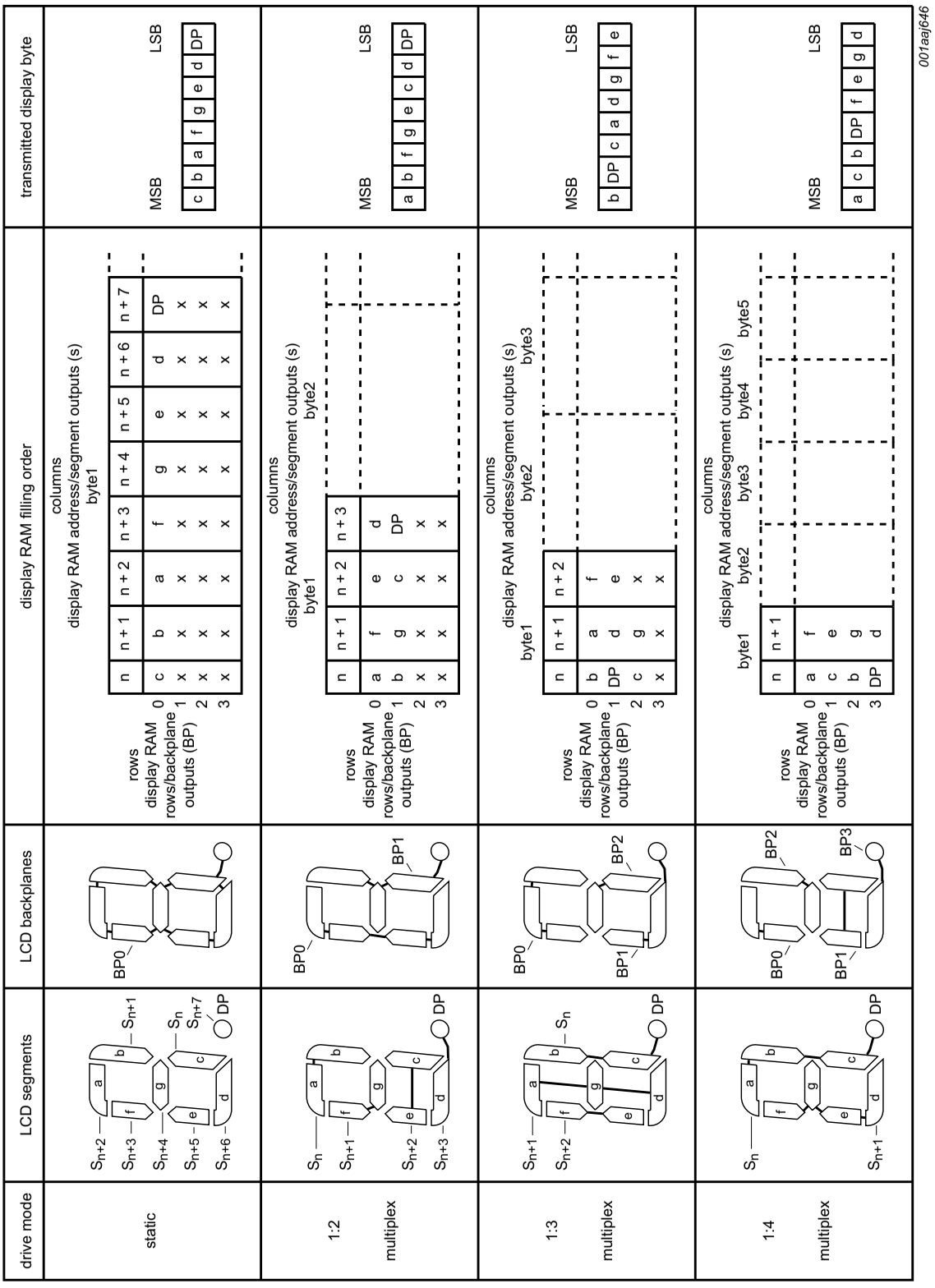
Fig 11. Display RAM bitmap

When display data is transmitted to the PCF85162, the display bytes received are stored in the display RAM in accordance with the selected LCD drive mode. The data is stored as it arrives and depending on the current multiplex drive mode the bits are stored singularly, in pairs, triples or quadruples. To illustrate the filling order, an example of a 7-segment numeric display showing all drive modes is given in Figure 12; the RAM filling organization depicted applies equally to other LCD types.

- In static drive mode the eight transmitted data bits are placed into row 0 as one byte
- In 1:2 multiplex drive mode the eight transmitted data bits are placed in pairs into row 0 and 1 as four successive 2-bit RAM words
- In 1:3 multiplex drive mode the eight bits are placed in triples into row 0, 1, and 2 as three successive 3-bit RAM words, with bit 3 of the third address left unchanged. It is not recommended to use this bit in a display because of the difficult addressing. This last bit may, if necessary, be controlled by an additional transfer to this address, but care should be taken to avoid overwriting adjacent data because always full bytes are transmitted (see Section 7.6.4)
- In 1:4 multiplex drive mode, the eight transmitted data bits are placed in quadruples into row 0, 1, 2, and 3 as two successive 4-bit RAM words

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.



x = data bit unchanged.

Fig 12. Relationship between LCD layout, drive mode, display RAM filling order, and display data transmitted over the I²C-bus

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

7.6.1 Data pointer

The addressing mechanism for the display RAM is realized using the data pointer. This allows the loading of an individual display data byte, or a series of display data bytes, into any location of the display RAM. The sequence commences with the initialization of the data pointer by the load-data-pointer command (see Table 8). Following this command, an arriving data byte is stored at the display RAM address indicated by the data pointer. The filling order is shown in Figure 12.

After each byte is stored, the content of the data pointer is automatically incremented by a value dependent on the selected LCD drive mode:

- In static drive mode by eight
- In 1:2 multiplex drive mode by four
- In 1:3 multiplex drive mode by three
- In 1:4 multiplex drive mode by two

If an I^2C-bus data access terminates early then the state of the data pointer is unknown. Consequently, the data pointer must be rewritten prior to further RAM accesses.

7.6.2 Subaddress counter

The storage of display data is determined by the contents of the subaddress counter. Storage is allowed only when the content of the subaddress counter match with the hardware subaddress applied to A0, A1, and A2. The subaddress counter value is defined by the device-select command (see Table 9). If the content of the subaddress counter and the hardware subaddress do not match then data storage is inhibited but the data pointer is incremented as if data storage had taken place. The subaddress counter is also incremented when the data pointer overflows.

7.6.3 RAM addressing in cascaded applications

In cascaded applications each PCF85162 in the cascade must be addressed separately. Initially, the first PCF85162 is selected by sending the device-select command matching the first device's hardware subaddress. Then the data pointer is set to the preferred display RAM address by sending the load-data-pointer command.

Once the display RAM of the first PCF85162 has been written, the second PCF85162 is selected by sending the device-select command again. This time however the command matches the second device's hardware subaddress. Next the load-data-pointer command is sent to select the preferred display RAM address of the second PCF85162.

This last step is very important because during writing data to the first PCF85162, the data pointer of the second PCF85162 is incremented. In addition, the hardware subaddress should not be changed whilst the device is being accessed on the I^2C-bus interface.

7.6.4 RAM writing in 1:3 multiplex drive mode

In 1:3 multiplex drive mode, the RAM is written as shown in Table 15 (see Figure 12 as well).

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

Table 15. Standard RAM filling in 1:3 multiplex drive mode

*Assumption: BP2/S2, BP2/S5, BP2/S8 etc. **are not connected** to any segments/elements on the display.*

Display RAM bits (rows)/ backplane outputs (BPn)	Display RAM addresses (columns)/segment outputs (Sn)										
	0	**1**	**2**	**3**	**4**	**5**	**6**	**7**	**8**	**9**	**:**
0	a7	a4	a1	b7	b4	b1	c7	c4	c1	d7	:
1	a6	a3	a0	b6	b3	b0	c6	c3	c0	d6	:
2	a5	a2	-	b5	b2	-	c5	c2	-	d5	:
3	-	-	-	-	-	-	-	-	-	-	:

If the bit at position BP2/S2 would be written by a second byte transmitted, then the mapping of the segment bits would change as illustrated in Table 16.

Table 16. Entire RAM filling by rewriting in 1:3 multiplex drive mode

*Assumption: BP2/S2, BP2/S5, BP2/S8 etc. **are connected** to segments/elements on the display.*

Display RAM bits (rows)/ backplane outputs (BPn)	Display RAM addresses (columns)/segment outputs (Sn)										
	0	**1**	**2**	**3**	**4**	**5**	**6**	**7**	**8**	**9**	**:**
0	a7	a4	a1/b7	b4	b1/c7	c4	c1/d7	d4	d1/e7	e4	:
1	a6	a3	a0/b6	b3	b0/c6	c3	c0/d6	d3	d0/e6	e3	:
2	a5	a2	b5	b2	c5	c2	d5	d2	e5	e2	:
3	-	-	-	-	-	-	-	-	-	-	:

In the case described in Table 16 the RAM has to be written entirely and BP2/S2, BP2/S5, BP2/S8 etc. have to be connected to segments/elements on the display. This can be achieved by a combination of writing and rewriting the RAM like follows:

- In the first write to the RAM, bits a7 to a0 are written
- The data-pointer (see Section 7.6.1 on page 22) has to be set to the address of bit a1
- In the second write, bits b7 to b0 are written, overwriting bits a1 and a0 with bits b7 and b6
- The data-pointer has to be set to the address of bit b1
- In the third write, bits c7 to c0 are written, overwriting bits b1 and b0 with bits c7 and c6

Depending on the method of writing to the RAM (standard or entire filling by rewriting), some segments/elements remain unused or can be used, but it has to be considered in the module layout process as well as in the driver software design.

7.6.5 Bank selection

7.6.5.1 Output bank selector

The output bank selector (see Table 10) selects one of the four rows per display RAM address for transfer to the display register. The actual row selected depends on the particular LCD drive mode in operation and on the instant in the multiplex sequence.

- In 1:4 multiplex mode, all RAM addresses of row 0 are selected, these are followed by the contents of row 1, 2, and then 3

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

- In 1:3 multiplex mode, rows 0, 1, and 2 are selected sequentially
- In 1:2 multiplex mode, rows 0 and 1 are selected
- In static mode, row 0 is selected

The PCF85162 includes a RAM bank switching feature in the static and 1:2 multiplex drive modes. In the static drive mode, the bank-select command may request the contents of row 2 to be selected for display instead of the contents of row 0. In the 1:2 multiplex mode, the contents of rows 2 and 3 may be selected instead of rows 0 and 1. This gives the provision for preparing display information in an alternative bank and to be able to switch to it once it is assembled.

7.6.5.2 Input bank selector

The input bank selector loads display data into the display RAM in accordance with the selected LCD drive configuration. Display data can be loaded in row 2 in static drive mode or in rows 2 and 3 in 1:2 multiplex drive mode by using the bank-select command (see Table 10). The input bank selector functions independently to the output bank selector.

7.6.5.3 RAM bank switching

The PCF85162 includes a RAM bank switching feature in the static and 1:2 multiplex drive modes. A bank can be thought of as one RAM row or a collection of RAM rows (see Figure 13). The RAM bank switching gives the provision for preparing display information in an alternative bank and to be able to switch to it once it is complete.

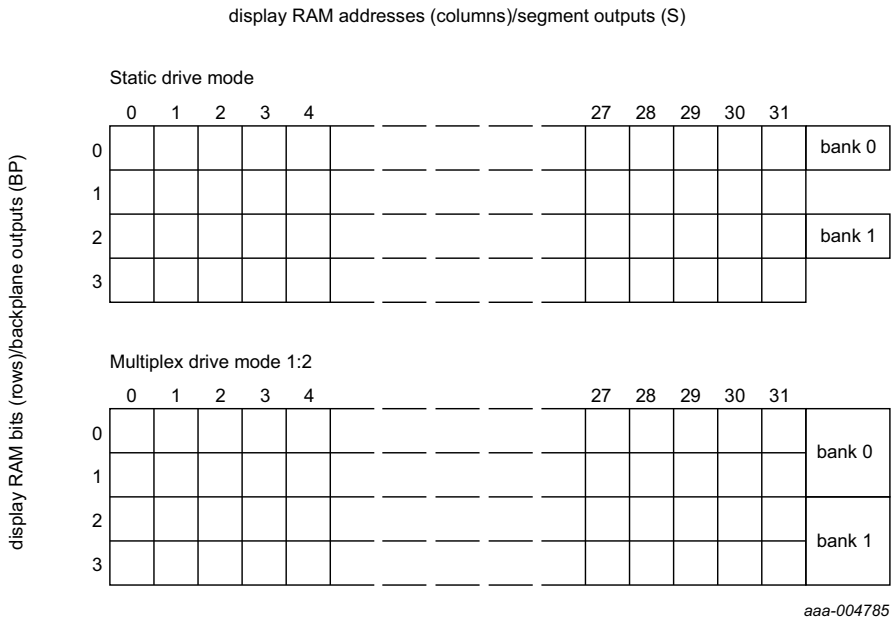


Fig 13. RAM banks in static and multiplex driving mode 1:2

There are two banks; bank 0 and bank 1. Figure 13 shows the location of these banks relative to the RAM map. Input and output banks can be set independently from one another with the Bank-select command (see Table 10 on page 7). Figure 14 shows the concept.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

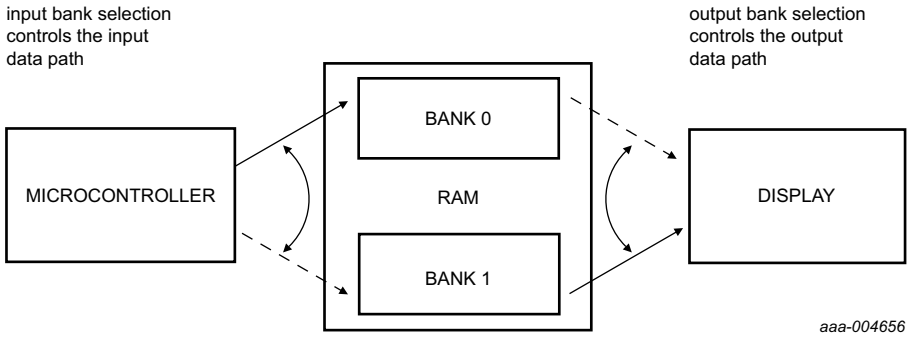


Fig 14. Bank selection

In the static drive mode, the bank-select command may request the contents of row 2 to be selected for display instead of the contents of row 0. In the 1:2 multiplex mode, the contents of rows 2 and 3 may be selected instead of rows 0 and 1. This gives the provision for preparing display information in an alternative bank and to be able to switch to it once it is assembled.

In Figure 15 an example is shown for 1:2 multiplex drive mode where the displayed data is read from the first two rows of the memory (bank 0), while the transmitted data is stored in the second two rows of the memory (bank 1).

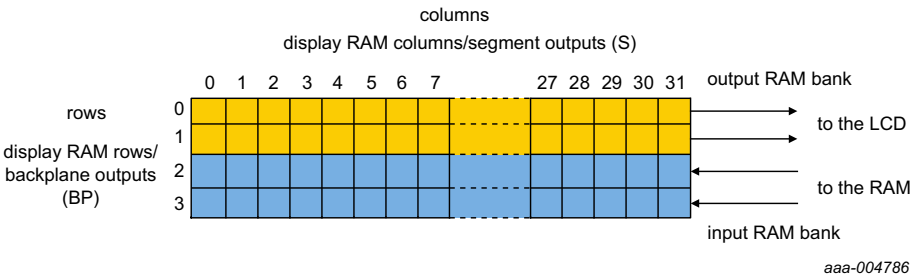


Fig 15. Example of the Bank-select command with multiplex drive mode 1:2

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

8. Characteristics of the I²C-bus

The I²C-bus is for bidirectional, two-line communication between different ICs or modules. The two lines are a Serial DAta line (SDA) and a Serial CLock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

8.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as a control signal (see Figure 16).

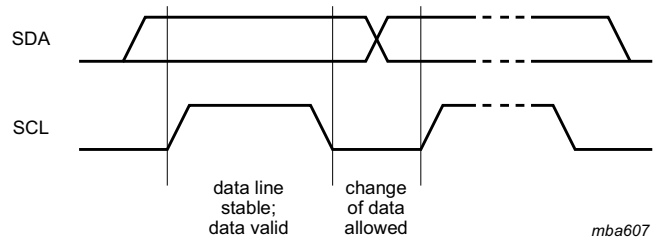


Fig 16. Bit transfer

8.2 START and STOP conditions

Both data and clock lines remain HIGH when the bus is not busy.

A HIGH-to-LOW transition of the data line while the clock is HIGH is defined as the START condition - S.

A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition - P.

The START and STOP conditions are illustrated in Figure 17.

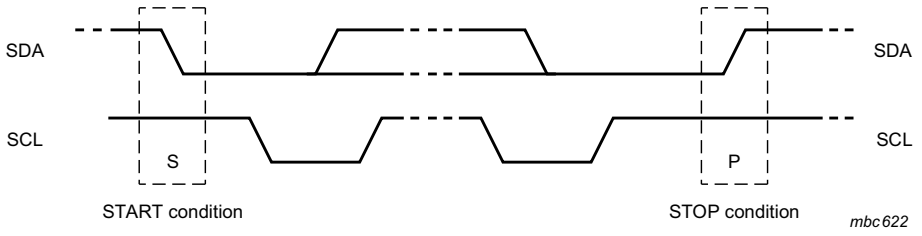


Fig 17. Definition of START and STOP conditions

8.3 System configuration

A device generating a message is a transmitter, a device receiving a message is the receiver. The device that controls the message is the master and the devices which are controlled by the master are the slaves. The system configuration is shown in Figure 18.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

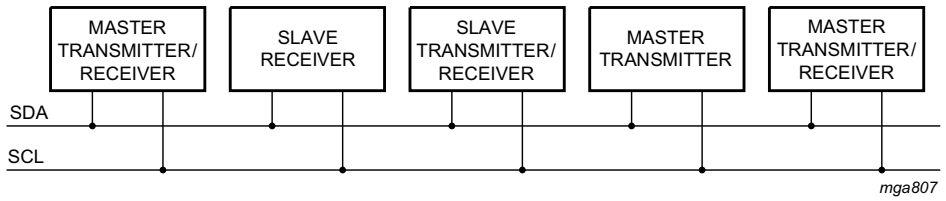


Fig 18. System configuration

8.4 Acknowledge

The number of data bytes transferred between the START and STOP conditions from transmitter to receiver is unlimited. Each byte of eight bits is followed by an acknowledge cycle.

- A slave receiver, which is addressed, must generate an acknowledge after the reception of each byte
- A master receiver must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter
- The device that acknowledges must pull-down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse (set-up and hold times must be taken into consideration)
- A master receiver must signal an end of data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event, the transmitter must leave the data line HIGH to enable the master to generate a STOP condition

Acknowledgement on the I^2C-bus is illustrated in Figure 19.

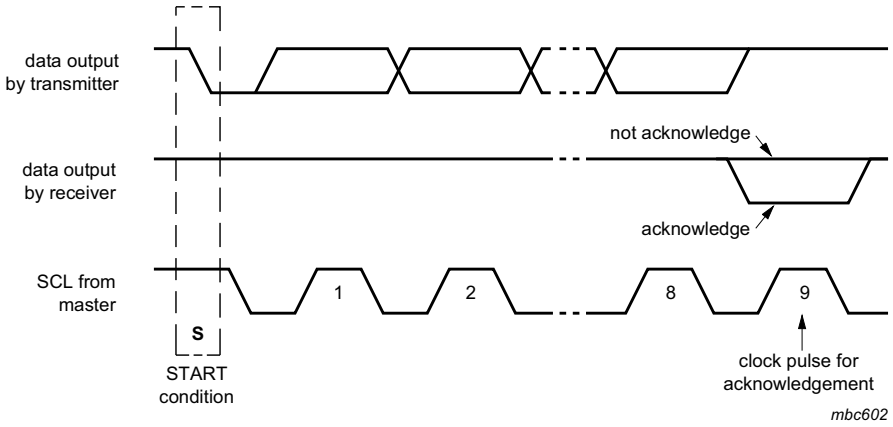


Fig 19. Acknowledgement of the I^2C-bus

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

8.5 I²C-bus controller

The PCF85162 acts as an I²C-bus slave receiver. It does not initiate I²C-bus transfers or transmit data to an I²C-bus master receiver. The only data output from the PCF85162 are the acknowledge signals of the selected devices. Device selection depends on the I²C-bus slave address, on the transferred command data and on the hardware subaddress.

In single device applications, the hardware subaddress inputs A0, A1, and A2 are normally tied to V_{SS} which defines the hardware subaddress 0. In multiple device applications A0, A1, and A2 are tied to V_{SS} or V_{DD} using a binary coding scheme, so that no two devices with a common I²C-bus slave address have the same hardware subaddress.

8.6 Input filters

To enhance noise immunity in electrically adverse environments, RC low-pass filters are provided on the SDA and SCL lines.

8.7 I²C-bus protocol

Two I²C-bus slave addresses (0111 000 and 0111 001) are used to address the PCF85162. The entire I²C-bus slave address byte is shown in Table 17.

Table 17. I²C slave address byte

	Slave address							
Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
	MSB							**LSB**
	0	1	1	1	0	0	SA0	R/$\overline{W}$

The PCF85162 is a write-only device and will not respond to a read access, therefore bit 0 should always be logic 0. Bit 1 of the slave address byte that a PCF85162 will respond to, is defined by the level tied to its SA0 input (V_{SS} for logic 0 and V_{DD} for logic 1).

Having two reserved slave addresses allows the following on the same I²C-bus:

- Up to 16 PCF85162 for very large LCD applications
- The use of two types of LCD multiplex drive modes

The I²C-bus protocol is shown in Figure 20. The sequence is initiated with a START condition (S) from the I²C-bus master which is followed by one of the two possible PCF85162 slave addresses available. All PCF85162 whose SA0 inputs correspond to bit 0 of the slave address respond by asserting an acknowledge in parallel. This I²C-bus transfer is ignored by all PCF85162 whose SA0 inputs are set to the alternative level.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

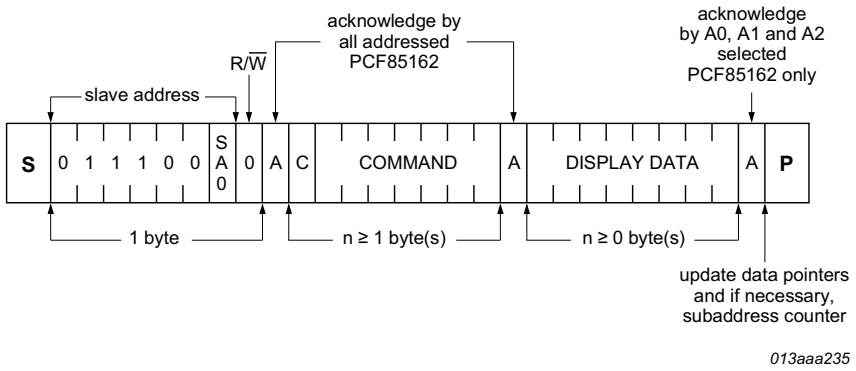


Fig 20. I²C-bus protocol

After an acknowledgement, one or more command bytes follow that define the status of each addressed PCF85162.

The last command byte sent is identified by resetting its most significant bit, continuation bit C (see Figure 21). The command bytes are also acknowledged by all addressed PCF85162 on the bus.

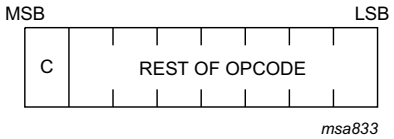


Fig 21. Format of command byte

After the last command byte, one or more display data bytes may follow. Display data bytes are stored in the display RAM at the address specified by the data pointer and the subaddress counter. Both data pointer and subaddress counter are automatically updated and the data directed to the intended PCF85162 device.

An acknowledgement after each byte is asserted only by the PCF85162 that are addressed via address lines A0, A1, and A2. After the last display byte, the I²C-bus master asserts a STOP condition (P). Alternately a START may be asserted to restart an I²C-bus access.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

9. Internal circuitry

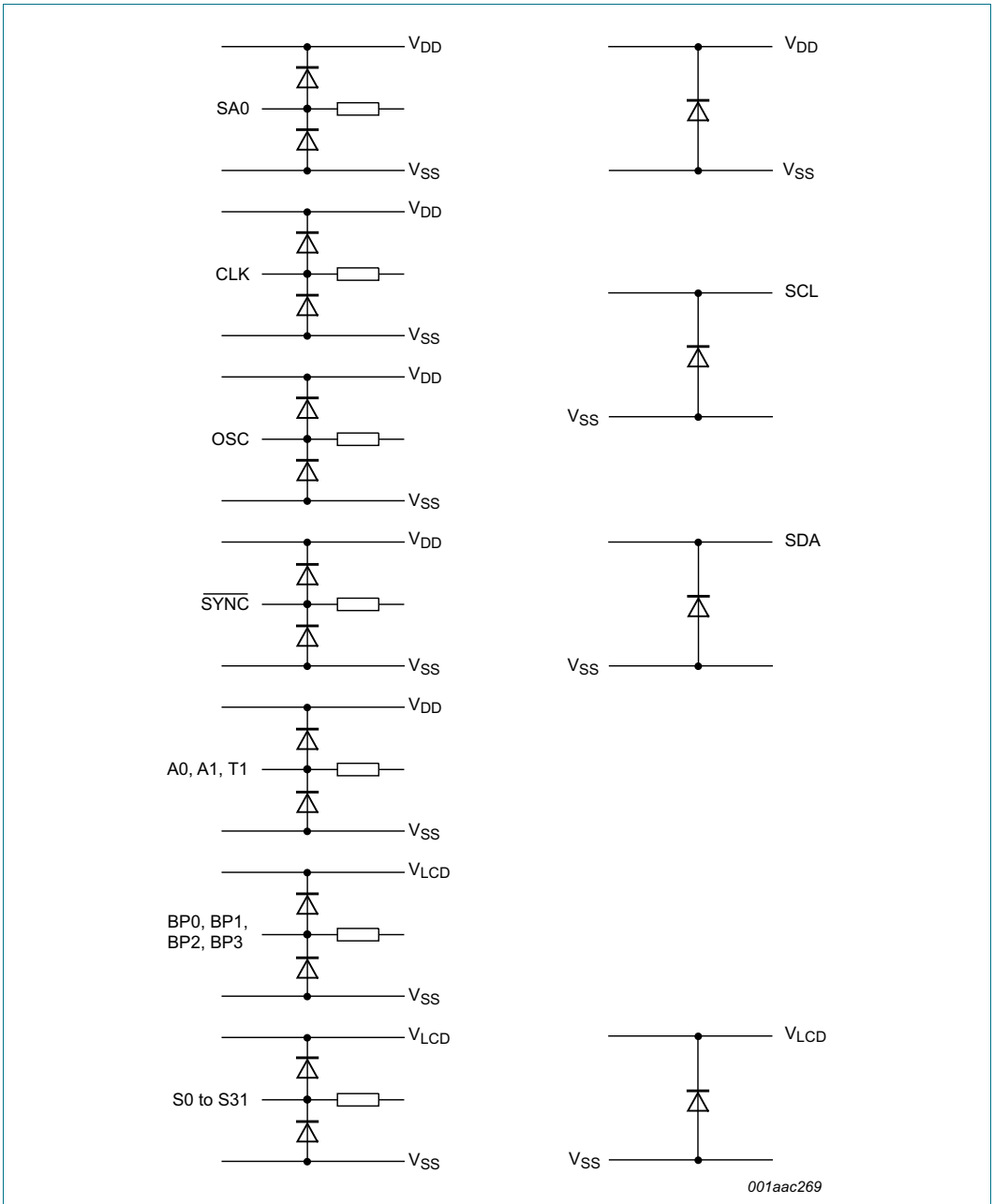


Fig 22. Device protection circuits

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

10. Safety notes

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

CAUTION



Static voltages across the liquid crystal display can build up when the LCD supply voltage (V_{LCD}) is on while the IC supply voltage (V_{DD}) is off, or vice versa. This may cause unwanted display artifacts. To avoid such artifacts, V_{LCD} and V_{DD} must be applied or removed together.

11. Limiting values

Table 18. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		−0.5	+6.5	V
V_{LCD}	LCD supply voltage		−0.5	+7.5	V
V_I	input voltage	on each of the pins CLK, SDA, SCL, $\overline{SYNC}$, SA0, OSC, A0 to A2	−0.5	+6.5	V
V_O	output voltage	on each of the pins S0 to S31, BP0 to BP3	−0.5	+7.5	V
I_I	input current		−10	+10	mA
I_O	output current		−10	+10	mA
I_{DD}	supply current		−50	+50	mA
$I_{DD(LCD)}$	LCD supply current		−50	+50	mA
I_{SS}	ground supply current		−50	+50	mA
P_{tot}	total power dissipation		-	400	mW
P_o	output power		-	100	mW
V_{ESD}	electrostatic discharge voltage	HBM [1]	-	±3500	V
		CDM [2]	-	±1750	V
I_{lu}	latch-up current	[3]	-	100	mA
T_{stg}	storage temperature	[4]	−65	+150	°C
T_{amb}	ambient temperature	operating device	−40	+85	°C

[1] Pass level; Human Body Model (HBM), according to Ref. 6 “JESD22-A114”.

[2] Pass level; Charged-Device Model (CDM), according to Ref. 7 “JESD22-C101”.

[3] Pass level; latch-up testing according to Ref. 8 “JESD78” at maximum ambient temperature ($T_{amb(max)}$).

[4] According to the store and transport requirements (see Ref. 12 “UM10569”) the devices have to be stored at a temperature of +8 °C to +45 °C and a humidity of 25 % to 75 %.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

12. Static characteristics

Table 19. Static characteristics

V_{DD} = 1.8 V to 5.5 V; V_{SS} = 0 V; V_{LCD} = 2.5 V to 6.5 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supplies						
V_{DD}	supply voltage		1.8	-	5.5	V
V_{LCD}	LCD supply voltage	[1]	2.5	-	6.5	V
I_{DD}	supply current	$f_{clk(ext)}$ = 1536 Hz [2][3]	-	3.5	7	µA
		V_{DD} = 3.0 V; T_{amb} = 25 °C	-	2.7	-	µA
$I_{DD(LCD)}$	LCD supply current	$f_{clk(ext)}$ = 1536 Hz [2]	-	23	32	µA
		V_{LCD} = 3.0 V; T_{amb} = 25 °C	-	13	-	µA
Logic[4]						
$V_{P(POR)}$	power-on reset supply voltage		1.0	1.3	1.6	V
V_{IL}	LOW-level input voltage	on pins CLK, $\overline{SYNC}$, OSC, A0 to A2, SA0, SCL, SDA	V_{SS}	-	$0.3V_{DD}$	V
V_{IH}	HIGH-level input voltage	on pins CLK, $\overline{SYNC}$, OSC, A0 to A2, SA0, SCL, SDA [5][6]	$0.7V_{DD}$	-	V_{DD}	V
I_{OL}	LOW-level output current	output sink current; V_{OL} = 0.4 V; V_{DD} = 5 V				
		on pins CLK and $\overline{SYNC}$	1	-	-	mA
		on pin SDA	3	-	-	mA
$I_{OH(CLK)}$	HIGH-level output current on pin CLK	output source current; V_{OH} = 4.6 V; V_{DD} = 5 V	1	-	-	mA
I_L	leakage current	$V_I = V_{DD}$ or V_{SS}; on pins CLK, SCL, SDA, A0 to A2, and SA0	−1	-	+1	µA
$I_{L(OSC)}$	leakage current on pin OSC	$V_I = V_{DD}$	−1	-	+1	µA
C_I	input capacitance	[7]	-	-	7	pF

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

Table 19. Static characteristics *...continued*

V_{DD} = 1.8 V to 5.5 V; V_{SS} = 0 V; V_{LCD} = 2.5 V to 6.5 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
LCD outputs						
ΔV_O	output voltage variation	on pins BP0 to BP3 and S0 to S31	−100	-	+100	mV
R_O	output resistance	V_{LCD} = 5 V [8]				
		on pins BP0 to BP3	-	1.5	-	kΩ
		on pins S0 to S31	-	6.0	-	kΩ

[1] $V_{LCD} > 3$ V for $\frac{1}{3}$ bias.

[2] LCD outputs are open-circuit; inputs at V_{SS} or V_{DD}; external clock with 50 % duty factor; I^2C-bus inactive.

[3] For typical values, see Figure 23.

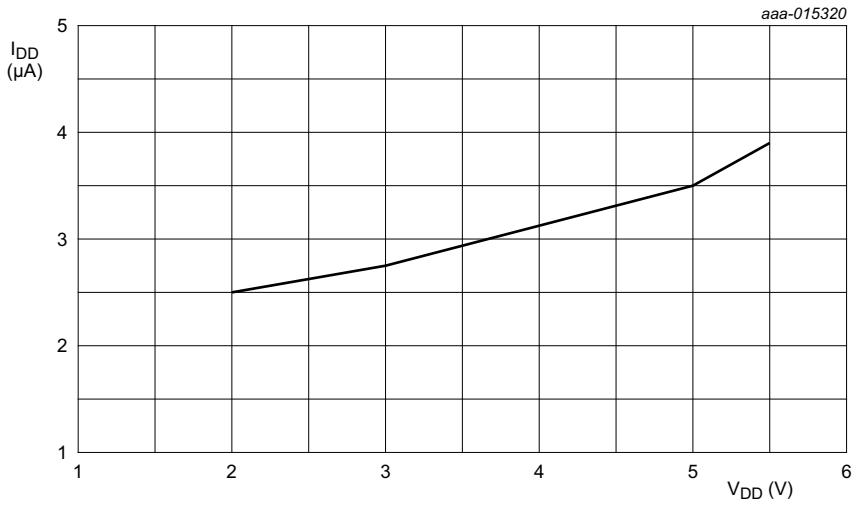
[4] The I^2C-bus interface of PCF85162 is 5 V tolerant.

[5] When tested, I^2C pins SCL and SDA have no diode to V_{DD} and may be driven to the V_I limiting values given in Table 18 (see Figure 22 as well).

[6] Propagation delay of driver between clock (CLK) and LCD driving signals.

[7] Periodically sampled, not 100 % tested.

[8] Outputs measured one at a time.



T_{amb} = 30 °C; 1:4 multiplex drive mode; V_{LCD} = 6.5 V; $f_{clk(ext)}$ = 1.536 kHz; all RAM written with logic 1; no display connected; I^2C-bus inactive.

Fig 23. Typical I_{DD} with respect to V_{DD}

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

13. Dynamic characteristics

Table 20. Dynamic characteristics

V_{DD} = 1.8 V to 5.5 V; V_{SS} = 0 V; V_{LCD} = 2.5 V to 6.5 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Clock						
$f_{clk(int)}$	internal clock frequency	[1]	1440	1850	2640	Hz
$f_{clk(ext)}$	external clock frequency		960	-	2640	Hz
f_{fr}	frame frequency	internal clock	60	77	110	Hz
		external clock	40	-	110	Hz
$t_{clk(H)}$	HIGH-level clock time		60	-	-	µs
$t_{clk(L)}$	LOW-level clock time		60	-	-	µs
Synchronization						
$t_{PD(SYNC_N)}$	$\overline{SYNC}$ propagation delay		-	30	-	ns
t_{SYNC_NL}	$\overline{SYNC}$ LOW time		1	-	-	µs
$t_{PD(drv)}$	driver propagation delay	V_{LCD} = 5 V [2]	-	-	30	µs
I^2C-bus[3]						
Pin SCL						
f_{SCL}	SCL clock frequency		-	-	400	kHz
t_{LOW}	LOW period of the SCL clock		1.3	-	-	µs
t_{HIGH}	HIGH period of the SCL clock		0.6	-	-	µs
Pin SDA						
$t_{SU;DAT}$	data set-up time		100	-	-	ns
$t_{HD;DAT}$	data hold time		0	-	-	ns
Pins SCL and SDA						
t_{BUF}	bus free time between a STOP and START condition		1.3	-	-	µs
$t_{SU;STO}$	set-up time for STOP condition		0.6	-	-	µs
$t_{HD;STA}$	hold time (repeated) START condition		0.6	-	-	µs
$t_{SU;STA}$	set-up time for a repeated START condition		0.6	-	-	µs
t_r	rise time of both SDA and SCL signals	f_{SCL} = 400 kHz	-	-	0.3	µs
		f_{SCL} < 125 kHz	-	-	1.0	µs

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

Table 20. Dynamic characteristics *...continued*

V_{DD} = 1.8 V to 5.5 V; V_{SS} = 0 V; V_{LCD} = 2.5 V to 6.5 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_f	fall time of both SDA and SCL signals		-	-	0.3	µs
C_b	capacitive load for each bus line		-	-	400	pF
$t_{w(spike)}$	spike pulse width	on the I²C-bus	-	-	50	ns

[1] Typical output duty factor: 50 % measured at the CLK output pin.

[2] Not tested in production.

[3] All timing values are valid within the operating supply voltage and ambient temperature range and are referenced to V_{IL} and V_{IH} with an input voltage swing of V_{SS} to V_{DD}.

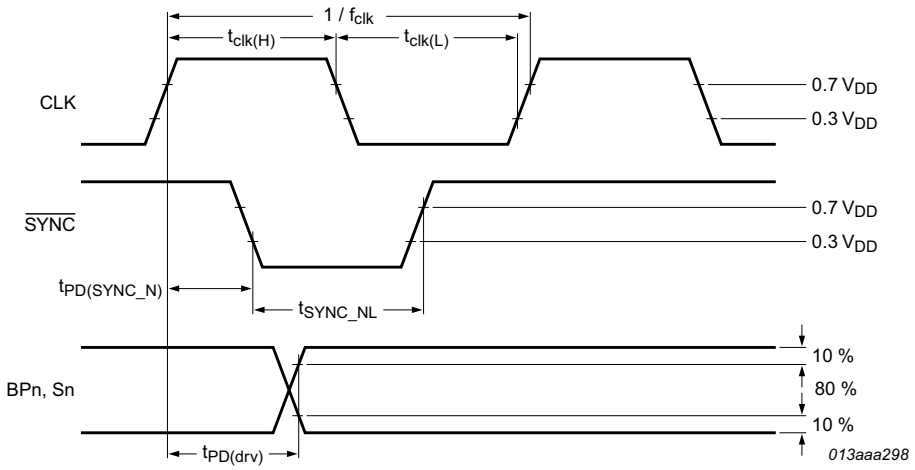


Fig 24. Driver timing waveforms

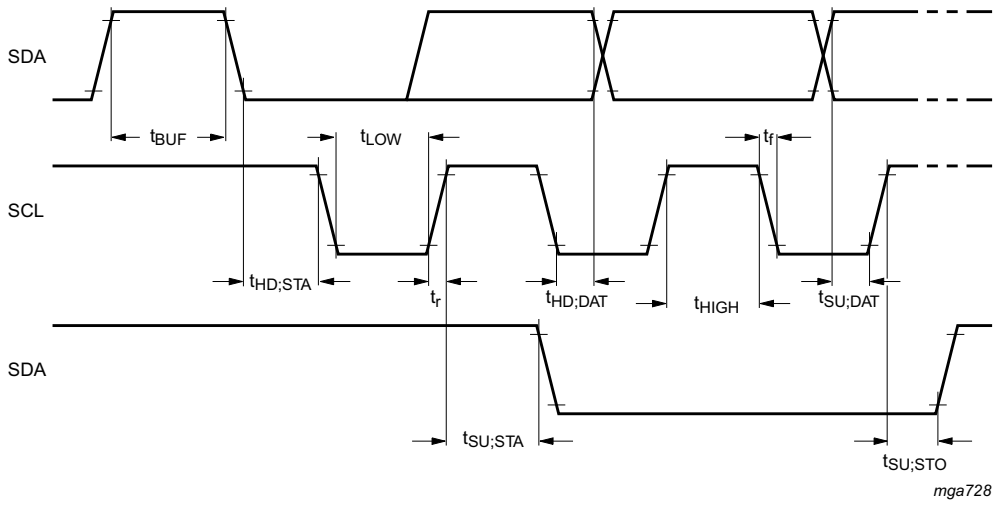


Fig 25. I²C-bus timing waveforms

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

14. Application information

14.1 Cascaded operation

Large display configurations of up to 16 PCF85162 can be recognized on the same I^2C-bus by using the 3-bit hardware subaddress (A0, A1, and A2) and the programmable I^2C-bus slave address (SA0).

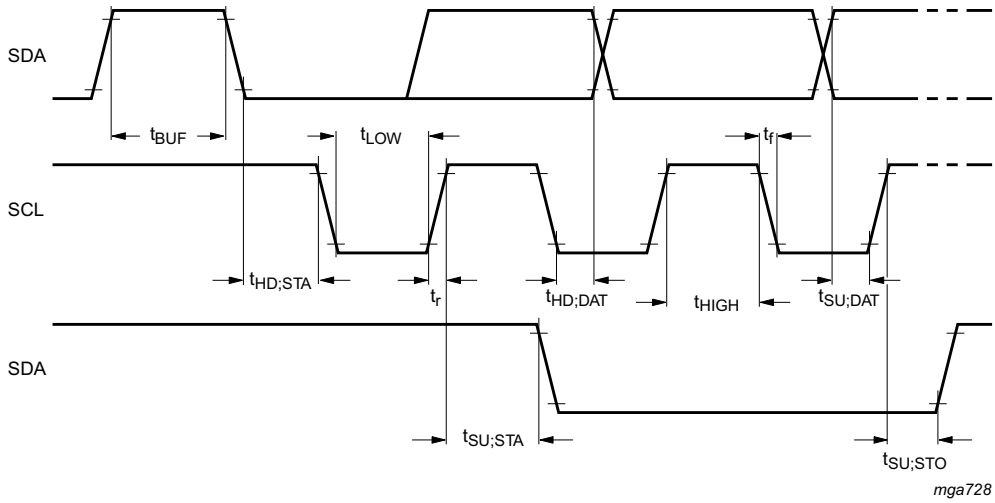
Table 21. Addressing cascaded PCF85162

Cluster	Bit SA0	Pin A2	Pin A1	Pin A0	Device
1	0	0	0	0	0
		0	0	1	1
		0	1	0	2
		0	1	1	3
		1	0	0	4
		1	0	1	5
		1	1	0	6
		1	1	1	7
2	1	0	0	0	8
		0	0	1	9
		0	1	0	10
		0	1	1	11
		1	0	0	12
		1	0	1	13
		1	1	0	14
		1	1	1	15

When cascaded PCF85162 are synchronized, they can share the backplane signals from one of the devices in the cascade. Such an arrangement is cost-effective in large LCD applications since the backplane outputs of only one device need to be through-plated to the backplane electrodes of the display. The other PCF85162 of the cascade contribute additional segment outputs. The backplanes can either be connected together to enhance the drive capability or some can be left open-circuit (such as the ones from the slave in Figure 26) or just some of the master and some of the slave will be taken to facilitate the layout of the display.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.



(1) Is master (OSC connected to V_{SS}).

(2) Is slave (OSC connected to V_{DD}).

Fig 26. Cascaded PCF85162 configuration

The $\overline{SYNC}$ line is provided to maintain the correct synchronization between all cascaded PCF85162. Synchronization is guaranteed after a power-on reset. The only time that $\overline{SYNC}$ is likely to be needed is if synchronization is accidentally lost (e.g. by noise in adverse electrical environments or by defining a multiplex drive mode when PCF85162 with different SA0 levels are cascaded).

$\overline{SYNC}$ is organized as an input/output pin. The output selection is realized as an open-drain driver with an internal pull-up resistor. A PCF85162 asserts the $\overline{SYNC}$ line at the onset of its last active backplane signal and monitors the $\overline{SYNC}$ line at all other times. If synchronization in the cascade is lost, it is restored by the first PCF85162 to assert $\overline{SYNC}$. The timing relationship between the backplane waveforms and the $\overline{SYNC}$ signal for the various drive modes of the PCF85162 are shown in Figure 27.

The contact resistance between the $\overline{SYNC}$ on each cascaded device must be controlled. If the resistance is too high, the device is not able to synchronize properly; this is particularly applicable to chip-on-glass applications. The maximum $\overline{SYNC}$ contact resistance allowed for the number of devices in cascade is given in Table 22.

Table 22. $\overline{SYNC}$ contact resistance

Number of devices	Maximum contact resistance
2	6 kΩ
3 to 5	2.2 kΩ
6 to 10	1.2 kΩ
10 to 16	700 Ω

The PCF85162 can always be cascaded with other devices of the same type or conditionally with other devices of the same family. This allows optimal drive selection for a given number of pixels to display. Figure 24 and Figure 27 show the timing of the synchronization signals.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

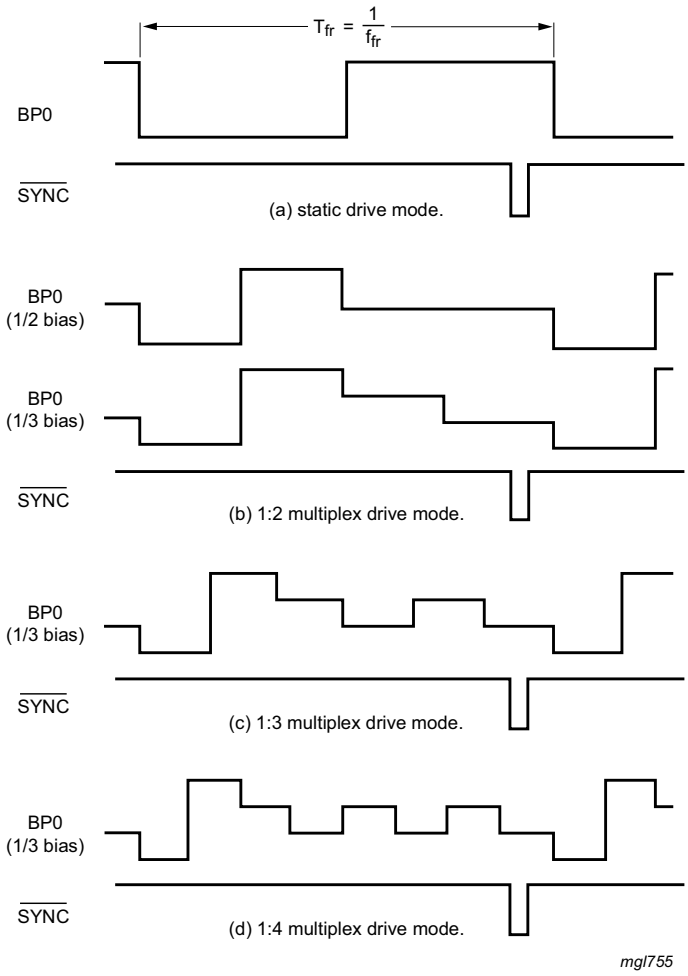


Fig 27. Synchronization of the cascade for the various PCF85162 drive modes

Only one master but multiple slaves are allowed in a cascade. All devices in the cascade have to use the same clock whether it is supplied externally or provided by the master.

If an external clock source is used, all PCF85162 in the cascade must be configured such as to receive the clock from that external source (pin OSC connected to V_{DD}). Thereby it must be ensured that the clock tree is designed such that on all PCF85162 the clock propagation delay from the clock source to all PCF85162 in the cascade is as equal as possible since otherwise synchronization artefacts may occur.

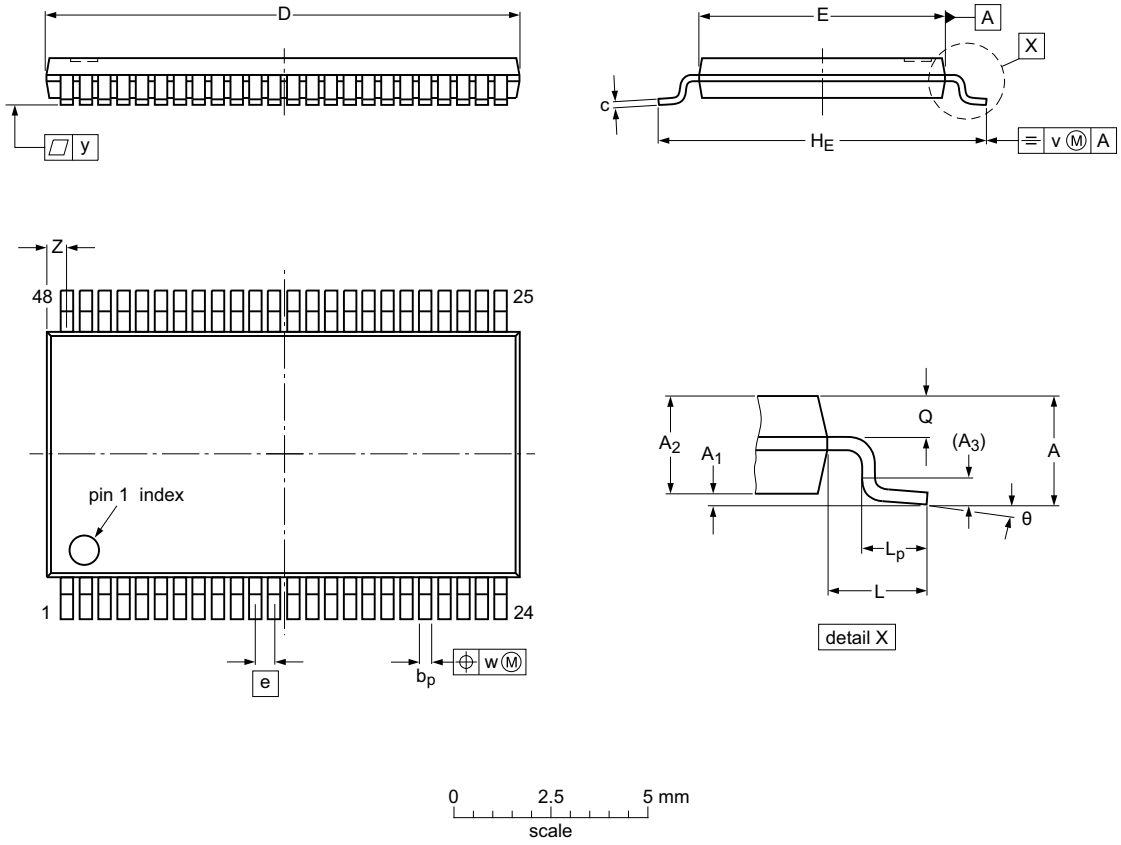
In mixed cascading configurations, care has to be taken that the specifications of the individual cascaded devices are met at all times.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

15. Package outline

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm **SOT362-1**



Dimensions (mm are the original dimensions)

Unit		A	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	Z	θ
mm	max	1.2	0.15	1.05	0.25	0.28	0.2	12.6	6.2	0.5	8.3	1	0.8	0.50	0.25	0.08	0.1	0.8	8°
	nom																		
	min		0.05	0.85		0.17	0.1	12.4	6.0		7.9		0.4	0.35				0.4	0°

Note
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot362-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT362-1		MO-153				~~03-02-19~~ 13-08-05

Fig 28. Package outline SOT362-1 (TSSOP48)

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

16. Handling information

All input and output pins are protected against ElectroStatic Discharge (ESD) under normal handling. When handling Metal-Oxide Semiconductor (MOS) devices ensure that all normal precautions are taken as described in *JESD625-A*, *IEC 61340-5* or equivalent standards.

17. Packing information

17.1 Tape and reel information

For tape and reel packing information, please see Ref. 10 “SOT362-1_118” on page 47.

18. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 “Surface mount reflow soldering description”*.

18.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

18.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

18.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

18.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 29) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 23 and 24

Table 23. SnPb eutectic process (from J-STD-020D)

Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm^3)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

Table 24. Lead-free process (from J-STD-020D)

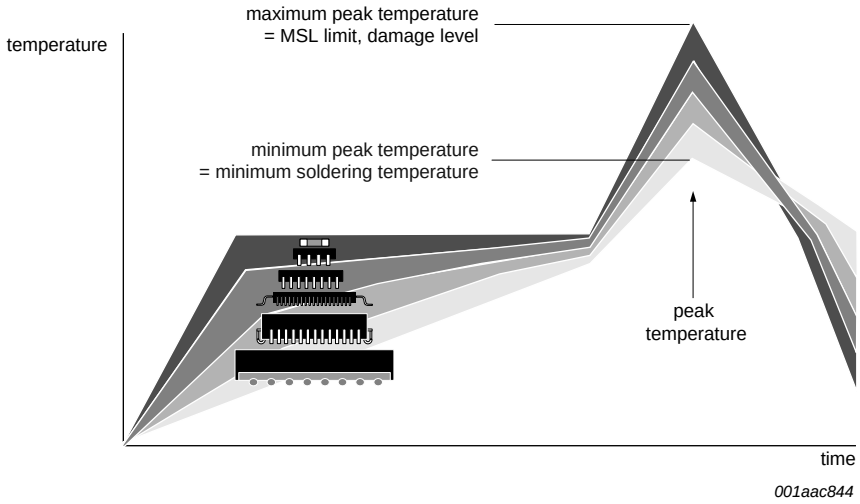
Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm^3)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 29.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.



MSL: Moisture Sensitivity Level

Fig 29. Temperature profiles for large and small components

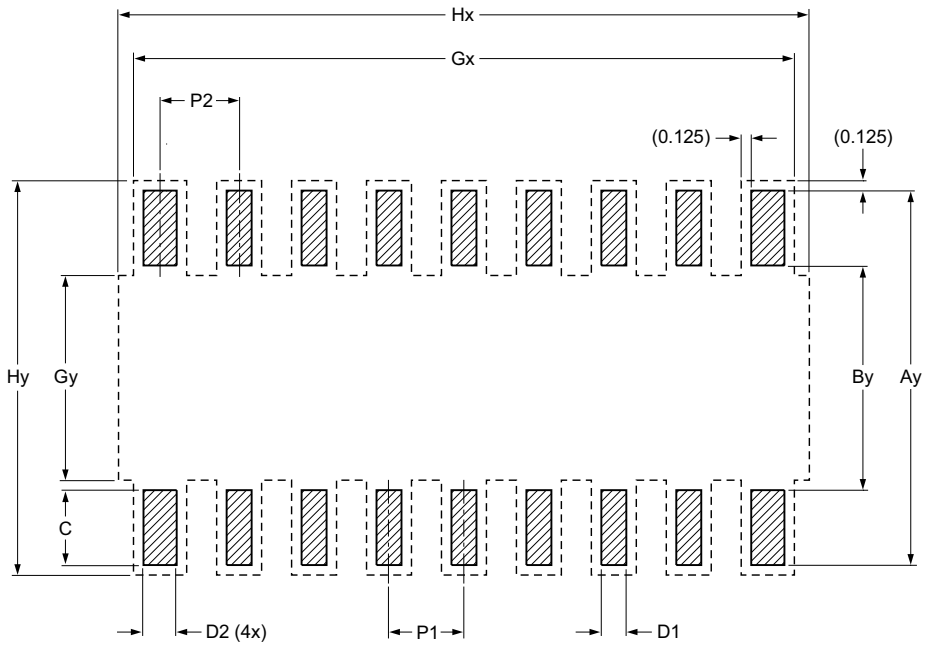
For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

19. Footprint information

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

Footprint information for reflow soldering of TSSOP48 package **SOT362-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	8.900	6.100	1.400	0.280	0.400	12.270	7.000	14.100	9.150

sot362-1_fr

Fig 30. Footprint information for reflow soldering of SOT362-1 (TSSOP48) of PCF85162T

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

20. Appendix

20.1 LCD segment driver selection

Table 25. Selection of LCD segment drivers

Type name	Number of elements at MUX							V_{DD} (V)	V_{LCD} (V)	f_{fr} (Hz)	V_{LCD} (V) charge pump	V_{LCD} (V) temperature compensat.	T_{amb} (°C)	Interface	Package	AEC-Q100
	1:1	1:2	1:3	1:4	1:6	1:8	1:9									
PCA8553DTT	40	80	120	160	-	-	-	1.8 to 5.5	1.8 to 5.5	32 to 256[1]	N	N	−40 to 105	I^2C / SPI	TSSOP56	Y
PCA8546ATT	-	-	-	176	-	-	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	N	N	−40 to 95	I^2C	TSSOP56	Y
PCA8546BTT	-	-	-	176	-	-	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	N	N	−40 to 95	SPI	TSSOP56	Y
PCA8547AHT	44	88	-	176	-	-	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	Y	Y	−40 to 95	I^2C	TQFP64	Y
PCA8547BHT	44	88	-	176	-	-	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	Y	Y	−40 to 95	SPI	TQFP64	Y
PCF85134HL	60	120	180	240	-	-	-	1.8 to 5.5	2.5 to 6.5	82	N	N	−40 to 85	I^2C	LQFP80	N
PCA85134H	60	120	180	240	-	-	-	1.8 to 5.5	2.5 to 8	82	N	N	−40 to 95	I^2C	LQFP80	Y
PCA8543AHL	60	120	-	240	-	-	-	2.5 to 5.5	2.5 to 9	60 to 300[1]	Y	Y	−40 to 105	I^2C	LQFP80	Y
PCF8545ATT	-	-	-	176	252	320	-	1.8 to 5.5	2.5 to 5.5	60 to 300[1]	N	N	−40 to 85	I^2C	TSSOP56	N
PCF8545BTT	-	-	-	176	252	320	-	1.8 to 5.5	2.5 to 5.5	60 to 300[1]	N	N	−40 to 85	SPI	TSSOP56	N
PCF8536AT	-	-	-	176	252	320	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	N	N	−40 to 85	I^2C	TSSOP56	N
PCF8536BT	-	-	-	176	252	320	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	N	N	−40 to 85	SPI	TSSOP56	N
PCA8536AT	-	-	-	176	252	320	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	N	N	−40 to 95	I^2C	TSSOP56	Y
PCA8536BT	-	-	-	176	252	320	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	N	N	−40 to 95	SPI	TSSOP56	Y
PCF8537AH	44	88	-	176	276	352	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	Y	Y	−40 to 85	I^2C	TQFP64	N
PCF8537BH	44	88	-	176	276	352	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	Y	Y	−40 to 85	SPI	TQFP64	N
PCA8537AH	44	88	-	176	276	352	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	Y	Y	−40 to 95	I^2C	TQFP64	Y
PCA8537BH	44	88	-	176	276	352	-	1.8 to 5.5	2.5 to 9	60 to 300[1]	Y	Y	−40 to 95	SPI	TQFP64	Y
PCA9620H	60	120	-	240	320	480	-	2.5 to 5.5	2.5 to 9	60 to 300[1]	Y	Y	−40 to 105	I^2C	LQFP80	Y
PCA9620U	60	120	-	240	320	480	-	2.5 to 5.5	2.5 to 9	60 to 300[1]	Y	Y	−40 to 105	I^2C	Bare die	Y
PCF8576DU	40	80	120	160	-	-	-	1.8 to 5.5	2.5 to 6.5	77	N	N	−40 to 85	I^2C	Bare die	N
PCF8576EUG	40	80	120	160	-	-	-	1.8 to 5.5	2.5 to 6.5	77	N	N	−40 to 85	I^2C	Bare die	N
PCA8576FUG	40	80	120	160	-	-	-	1.8 to 5.5	2.5 to 8	200	N	N	−40 to 105	I^2C	Bare die	Y
PCF85133U	80	160	240	320	-	-	-	1.8 to 5.5	2.5 to 6.5	82, 110[2]	N	N	−40 to 85	I^2C	Bare die	N
PCA85133U	80	160	240	320	-	-	-	1.8 to 5.5	2.5 to 8	82, 110[2]	N	N	−40 to 95	I^2C	Bare die	Y

PCF85162

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

Table 25. Selection of LCD segment drivers *...continued*

Type name	Number of elements at MUX							V_{DD} (V)	V_{LCD} (V)	f_{fr} (Hz)	V_{LCD} (V) charge pump	V_{LCD} (V) temperature compensat.	T_{amb} (°C)	Interface	Package	AEC-Q100
	1:1	1:2	1:3	1:4	1:6	1:8	1:9									
PCA85233UG	80	160	240	320	-	-	-	1.8 to 5.5	2.5 to 8	150, 220[2]	N	N	−40 to 105	I^2C	Bare die	Y
PCF85132U	160	320	480	640	-	-	-	1.8 to 5.5	1.8 to 8	60 to 90[1]	N	N	−40 to 85	I^2C	Bare die	N
PCA8530DUG	102	204	-	408	-	-	-	2.5 to 5.5	4 to 12	45 to 300[1]	Y	Y	−40 to 105	I^2C / SPI	Bare die	Y
PCA85132U	160	320	480	640	-	-	-	1.8 to 5.5	1.8 to 8	60 to 90[1]	N	N	−40 to 95	I^2C	Bare die	Y
PCA85232U	160	320	480	640	-	-	-	1.8 to 5.5	1.8 to 8	117 to 176[1]	N	N	−40 to 95	I^2C	Bare die	Y
PCF8538UG	102	204	-	408	612	816	918	2.5 to 5.5	4 to 12	45 to 300[1]	Y	Y	−40 to 85	I^2C / SPI	Bare die	N
PCA8538UG	102	204	-	408	612	816	918	2.5 to 5.5	4 to 12	45 to 300[1]	Y	Y	−40 to 105	I^2C / SPI	Bare die	Y

[1] Software programmable.

[2] Hardware selectable.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

21. Abbreviations

Table 26. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
CDM	Charged Device Model
DC	Direct Current
HBM	Human Body Model
I^2C	Inter-Integrated Circuit
IC	Integrated Circuit
LCD	Liquid Crystal Display
LSB	Least Significant Bit
MSB	Most Significant Bit
MSL	Moisture Sensitivity Level
PCB	Printed-Circuit Board
POR	Power-On Reset
RAM	Random Access Memory
RC	Resistance and Capacitance
RMS	Root Mean Square
SCL	Serial CLock line
SDA	Serial DAta Line
SMD	Surface-Mount Device

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

22. References

[1] **AN10365 —** Surface mount reflow soldering description

[2] **AN10853 —** ESD and EMC sensitivity of IC

[3] **IEC 60134 —** Rating systems for electronic tubes and valves and analogous semiconductor devices

[4] **IEC 61340-5 —** Protection of electronic devices from electrostatic phenomena

[5] **IPC/JEDEC J-STD-020D —** Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices

[6] **JESD22-A114 —** Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)

[7] **JESD22-C101 —** Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components

[8] **JESD78 —** IC Latch-Up Test

[9] **JESD625-A —** Requirements for Handling Electrostatic-Discharge-Sensitive (ESDS) Devices

[10] **SOT362-1_118 —** TSSOP48; Reel pack; SMD, 13", packing information

[11] **UM10204 —** I^2C-bus specification and user manual

[12] **UM10569 —** Store and transport requirements

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

23. Revision history

Table 27. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCF85162 v.5	20141217	Product data sheet	-	PCF85162 v.4
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Changed I_{DD} and $I_{DD(LCD)}$ values in Table 19 • Changed $f_{clk(int)}$ typical value in Table 20 • Changed Section 17.1 • Adjusted Figure 23			
PCF85162 v.4	20120905	Product data sheet	-	PCF85162 v.3
PCF85162 v.3	20110616	Product data sheet	-	PCF85162 v.2
PCF85162 v.2	20100507	Product data sheet	-	PCF85162 v.1
PCF85162 v.1	20100107	Product data sheet	-	-

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

24. Legal information

24.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

24.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

24.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nxp.com/profile/terms, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

24.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

I^2C-bus — logo is a trademark of NXP Semiconductors N.V.

25. Contact information

For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

26. Tables

Table 1. Ordering information 2
Table 2. Ordering options 2
Table 3. Marking codes 2
Table 4. Pin description 5
Table 5. Definition of PCF85162 commands 5
Table 6. C bit description 6
Table 7. Mode-set command bit description 6
Table 8. Load-data-pointer command bit description 6
Table 9. Device-select command bit description 7
Table 10. Bank-select command bit description 7
Table 11. Blink-select command bit description 8
Table 12. Blink frequencies 9
Table 13. Selection of possible display configurations . . .10
Table 14. Biasing characteristics 12
Table 15. Standard RAM filling in 1:3 multiplex drive mode 23
Table 16. Entire RAM filling by rewriting in 1:3 multiplex drive mode 23
Table 17. I^2C slave address byte 28
Table 18. Limiting values 31
Table 19. Static characteristics 32
Table 20. Dynamic characteristics 34
Table 21. Addressing cascaded PCF85162 36
Table 22. $\overline{SYNC}$ contact resistance 37
Table 23. SnPb eutectic process (from J-STD-020D) . . .41
Table 24. Lead-free process (from J-STD-020D) 41
Table 25. Selection of LCD segment drivers 44
Table 26. Abbreviations 46
Table 27. Revision history 48

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

27. Figures

Fig 1. Block diagram of PCF85162 3
Fig 2. Pin configuration for TSSOP48 (PCF85162T) 4
Fig 3. Example of displays suitable for PCF85162 10
Fig 4. Typical system configuration 11
Fig 5. Electro-optical characteristic: relative transmission curve of the liquid 13
Fig 6. Static drive mode waveforms 14
Fig 7. Waveforms for the 1:2 multiplex drive mode with $\frac{1}{2}$ bias 15
Fig 8. Waveforms for the 1:2 multiplex drive mode with $\frac{1}{3}$ bias 16
Fig 9. Waveforms for the 1:3 multiplex drive mode with $\frac{1}{3}$ bias 17
Fig 10. Waveforms for the 1:4 multiplex drive mode with $\frac{1}{3}$ bias 18
Fig 11. Display RAM bitmap 20
Fig 12. Relationship between LCD layout, drive mode, display RAM filling order, and display data transmitted over the I^2C-bus 21
Fig 13. RAM banks in static and multiplex driving mode 1:2 24
Fig 14. Bank selection 25
Fig 15. Example of the Bank-select command with multiplex drive mode 1:2 25
Fig 16. Bit transfer 26
Fig 17. Definition of START and STOP conditions 26
Fig 18. System configuration 27
Fig 19. Acknowledgement of the I^2C-bus 27
Fig 20. I^2C-bus protocol 29
Fig 21. Format of command byte 29
Fig 22. Device protection circuits 30
Fig 23. Typical I_{DD} with respect to V_{DD} 33
Fig 24. Driver timing waveforms 35
Fig 25. I^2C-bus timing waveforms 35
Fig 26. Cascaded PCF85162 configuration 37
Fig 27. Synchronization of the cascade for the various PCF85162 drive modes 38
Fig 28. Package outline SOT362-1 (TSSOP48) 39
Fig 29. Temperature profiles for large and small components 42
Fig 30. Footprint information for reflow soldering of SOT362-1 (TSSOP48) of PCF85162T 43

All information provided in this document is subject to legal disclaimers.

© NXP Semiconductors N.V. 2014. All rights reserved.

28. Contents

1 General description 1
2 Features and benefits 1
3 Ordering information 2
3.1 Ordering options 2
4 Marking 2
5 Block diagram 3
6 Pinning information 4
6.1 Pinning 4
6.2 Pin description 5
7 Functional description 5
7.1 Commands of PCF85162 5
7.1.1 Command: mode-set 6
7.1.2 Command: load-data-pointer 6
7.1.3 Command: device-select 7
7.1.4 Command: bank-select 7
7.1.5 Command: blink-select 7
7.1.5.1 Blinking 8
7.2 Power-On Reset (POR) 9
7.3 Possible display configurations 10
7.3.1 LCD bias generator 11
7.3.2 Display register 11
7.3.3 LCD voltage selector 11
7.3.3.1 Electro-optical performance 13
7.3.4 LCD drive mode waveforms 14
7.3.4.1 Static drive mode 14
7.3.4.2 1:2 Multiplex drive mode 15
7.3.4.3 1:3 Multiplex drive mode 17
7.3.4.4 1:4 Multiplex drive mode 18
7.4 Oscillator 19
7.4.1 Internal clock 19
7.4.2 External clock 19
7.4.3 Timing 19
7.5 Backplane and segment outputs 19
7.5.1 Backplane outputs 19
7.5.2 Segment outputs 19
7.6 Display RAM 20
7.6.1 Data pointer 22
7.6.2 Subaddress counter 22
7.6.3 RAM addressing in cascaded applications . . . 22
7.6.4 RAM writing in 1:3 multiplex drive mode 22
7.6.5 Bank selection 23
7.6.5.1 Output bank selector 23
7.6.5.2 Input bank selector 24
7.6.5.3 RAM bank switching 24
8 Characteristics of the I²C-bus 26
8.1 Bit transfer 26
8.2 START and STOP conditions 26
8.3 System configuration 26
8.4 Acknowledge 27
8.5 I²C-bus controller 28
8.6 Input filters 28
8.7 I²C-bus protocol 28
9 Internal circuitry 30
10 Safety notes 31
11 Limiting values 31
12 Static characteristics 32
13 Dynamic characteristics 34
14 Application information 36
14.1 Cascaded operation 36
15 Package outline 39
16 Handling information 40
17 Packing information 40
17.1 Tape and reel information 40
18 Soldering of SMD packages 40
18.1 Introduction to soldering 40
18.2 Wave and reflow soldering 40
18.3 Wave soldering 41
18.4 Reflow soldering 41
19 Footprint information 42
20 Appendix 44
20.1 LCD segment driver selection 44
21 Abbreviations 46
22 References 47
23 Revision history 48
24 Legal information 49
24.1 Data sheet status 49
24.2 Definitions 49
24.3 Disclaimers 49
24.4 Trademarks 50
25 Contact information 50
26 Tables 51
27 Figures 52
28 Contents 53

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© NXP Semiconductors N.V. 2014. All rights reserved.

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 17 December 2014
Document identifier: PCF85162